



# M29W320DT M29W320DB

32 Mbit (4Mb x8 or 2Mb x16, Boot Block)

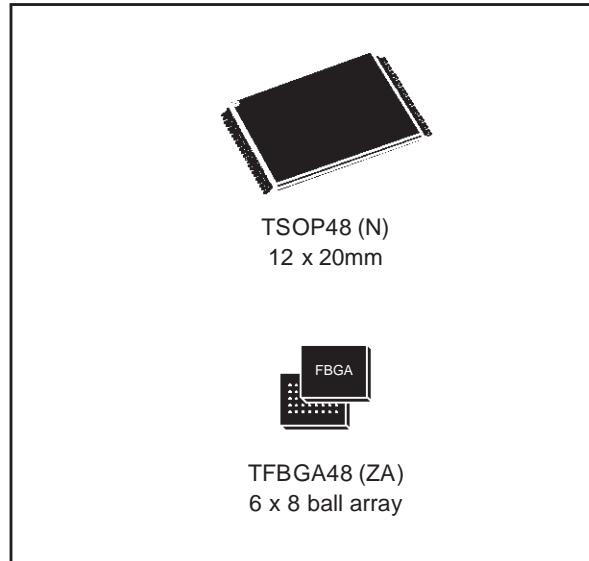
3V Supply Flash Memory

PRELIMINARY DATA

## FEATURES SUMMARY

- SUPPLY VOLTAGE
  - $V_{CC}$  = 2.7V to 3.6V for Program, Erase and Read
  - $V_{PP}$  = 12V for Fast Program (optional)
- ACCESS TIME: 70, 90ns
- PROGRAMMING TIME
  - 10 $\mu$ s per Byte/Word typical
- 67 MEMORY BLOCKS
  - 1 Boot Block (Top or Bottom Location)
  - 2 Parameter and 64 Main Blocks
- PROGRAM/ERASE CONTROLLER
  - Embedded Byte/Word Program algorithms
- ERASE SUSPEND and RESUME MODES
  - Read and Program another Block during Erase Suspend
- UNLOCK BYPASS PROGRAM COMMAND
  - Faster Production/Batch Programming
- $V_{PP}/\overline{WP}$  PIN for FAST PROGRAM and WRITE PROTECT
- TEMPORARY BLOCK UNPROTECTION MODE
- COMMON FLASH INTERFACE
  - 64 bit Security Code
- LOW POWER CONSUMPTION
  - Standby and Automatic Standby
- 100,000 PROGRAM/ERASE CYCLES per BLOCK
- ELECTRONIC SIGNATURE
  - Manufacturer Code: 0020h
  - Top Device Code M29W320DT: 22CAh
  - Bottom Device Code M29W320DB: 22CBh

Figure 1. Packages



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## SUMMARY DESCRIPTION

The M29W320D is a 32 Mbit (4Mb x8 or 2Mb x16) non-volatile memory that can be read, erased and reprogrammed. These operations can be performed using a single low voltage (2.7 to 3.6V) supply. On power-up the memory defaults to its Read mode where it can be read in the same way as a ROM or EPROM.

The memory is divided into blocks that can be erased independently so it is possible to preserve valid data while old data is erased. Each block can be protected independently to prevent accidental Program or Erase commands from modifying the memory. Program and Erase commands are written to the Command Interface of the memory. An on-chip Program/Erase Controller simplifies the process of programming or erasing the memory by taking care of all of the special operations that are required to update the memory contents. The end of a program or erase operation can be detected and any error conditions identified. The command set required to control the memory is consistent with JEDEC standards.

The device features an asymmetrical block architecture. The M29W320D has an array of 67 blocks: 4 Parameter Blocks and 63 Main Blocks. The x8 version has one 16KByte block, two 8KByte blocks, one 32KByte block and 63 Main Blocks of 64KBytes. The x16 version has one 8KWord block, two 4KWord blocks, one 16KWord block and 63 Main Blocks of 32KWord. M29W320DT locates the Parameter Blocks at the top of the memory address space while the M29W320DB locates the Parameter Blocks starting from the bottom. The memory maps are shown in Figures 5 and 6, Block Addresses.

Chip Enable, Output Enable and Write Enable signals control the bus operation of the memory. They allow simple connection to most microprocessors, often without additional logic.

The memory is offered in TSOP48 (12 x 20mm) and TFBGA48 (0.8mm pitch) packages. The memory is supplied with all the bits erased (set to '1').

Figure 2. Logic Diagram

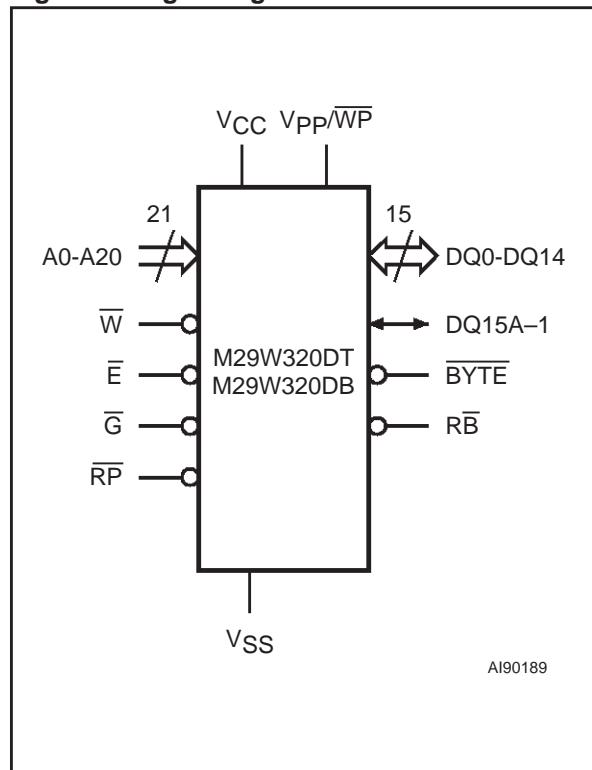
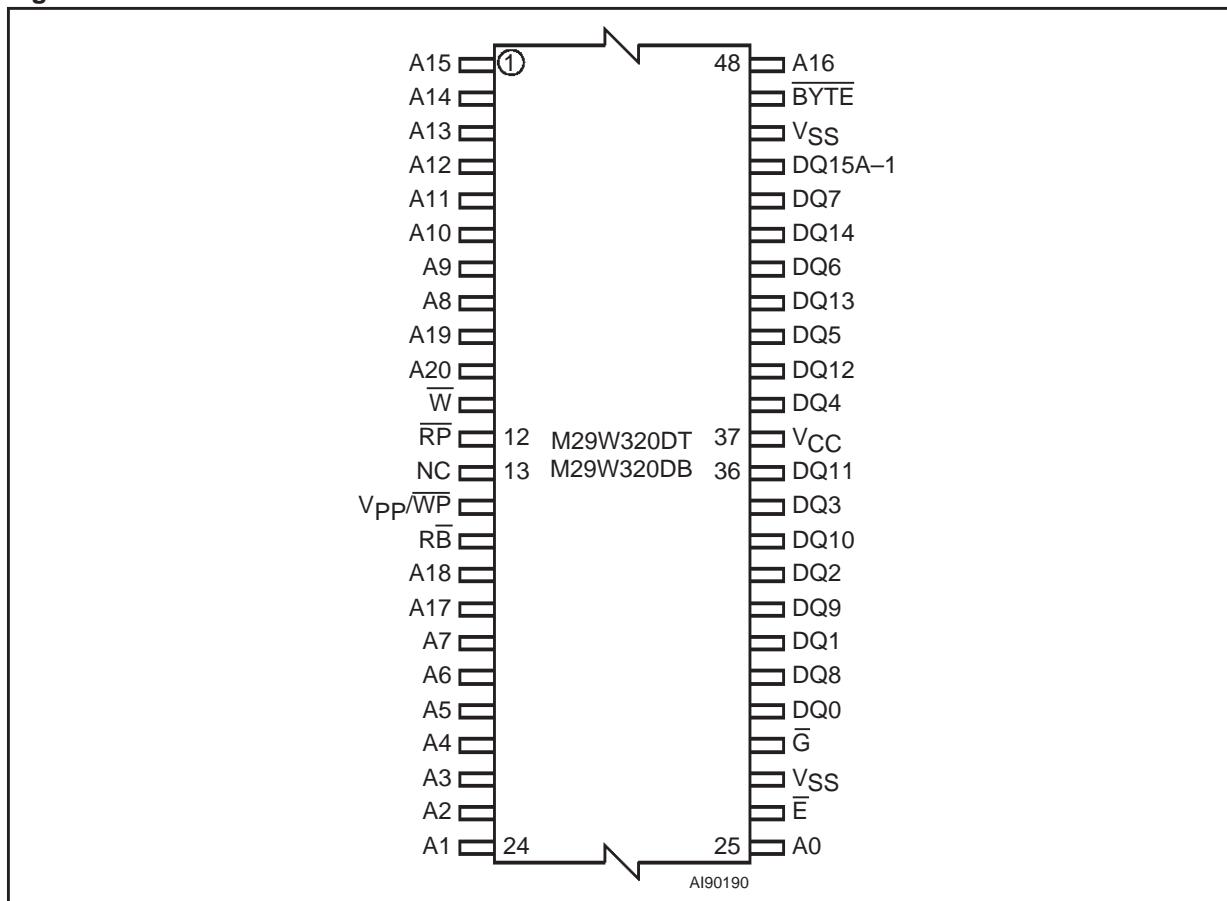


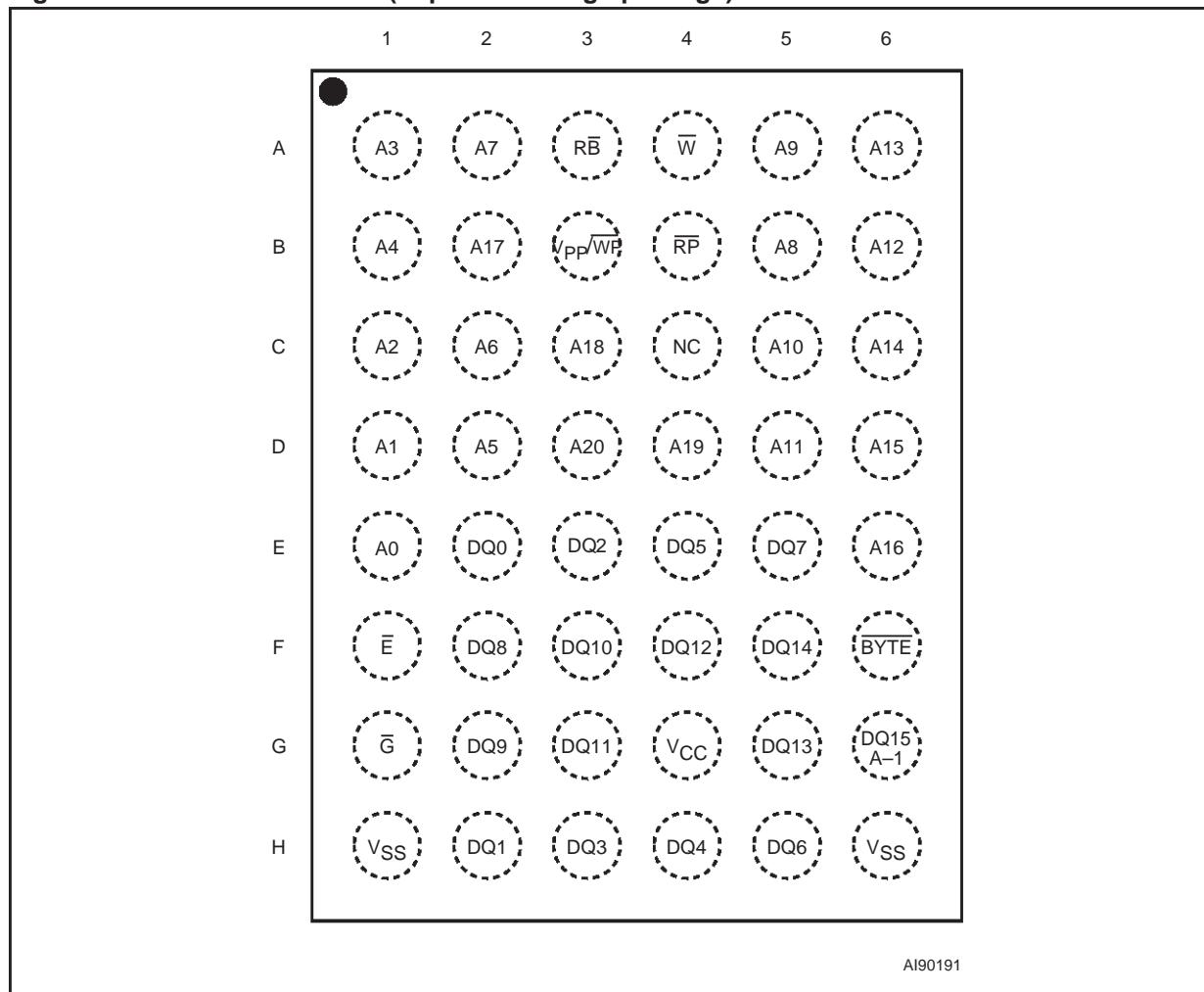
Table 1. Signal Names

A0-A20	Address Inputs
DQ0-DQ7	Data Inputs/Outputs
DQ8-DQ14	Data Inputs/Outputs
DQ15A-1	Data Input/Output or Address Input
$\bar{E}$	Chip Enable
$\bar{G}$	Output Enable
$\bar{W}$	Write Enable
$\bar{RP}$	Reset/Block Temporary Unprotect
$\bar{RB}$	Ready/Busy Output
$\bar{BYTE}$	Byte/Word Organization Select
V <sub>CC</sub>	Supply Voltage
V <sub>PP/WP</sub>	Supply Voltage for Fast Program (optional) or Write Protect
V <sub>SS</sub>	Ground
NC	Not Connected Internally

## M29W320DT, M29W320DB

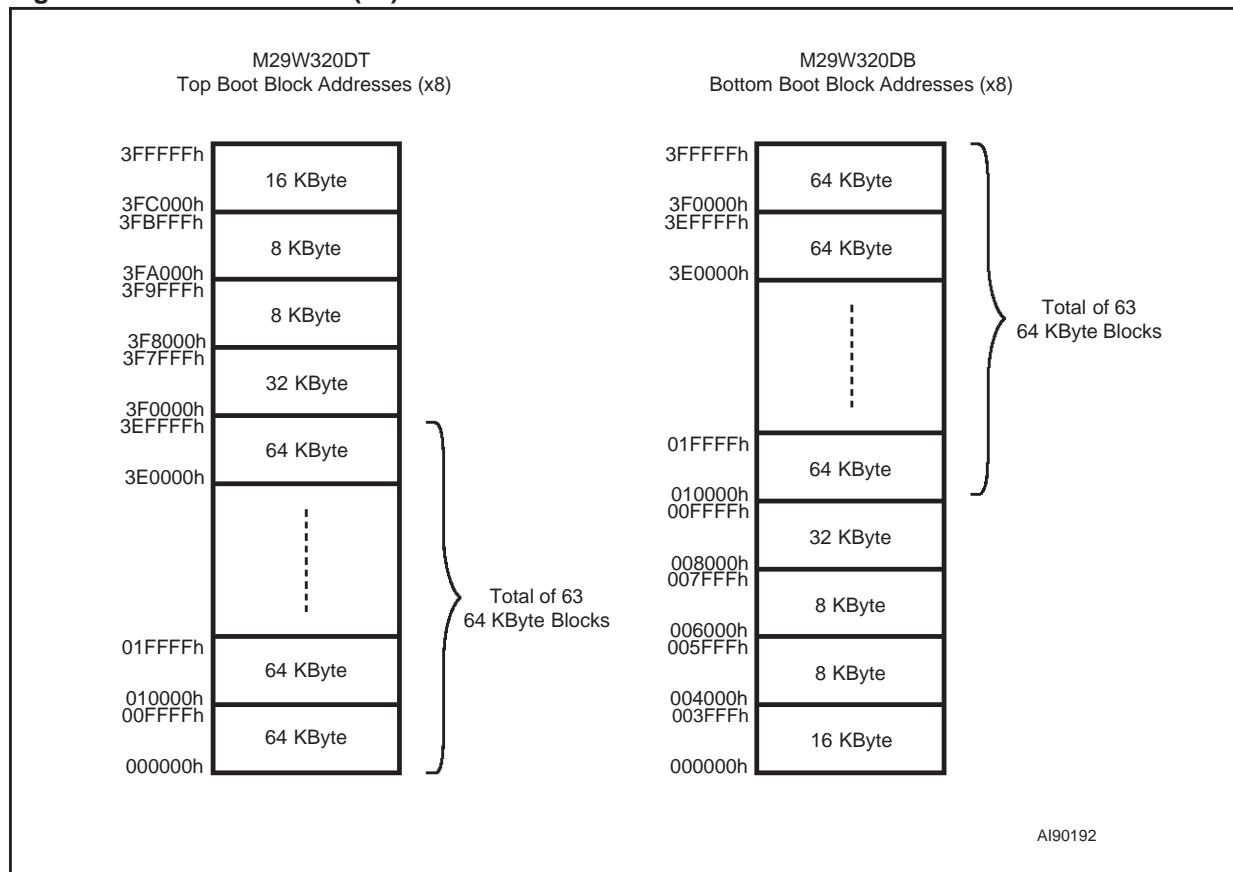
Figure 3. TSOP Connections



**Figure 4. TFBGA Connections (Top view through package)**

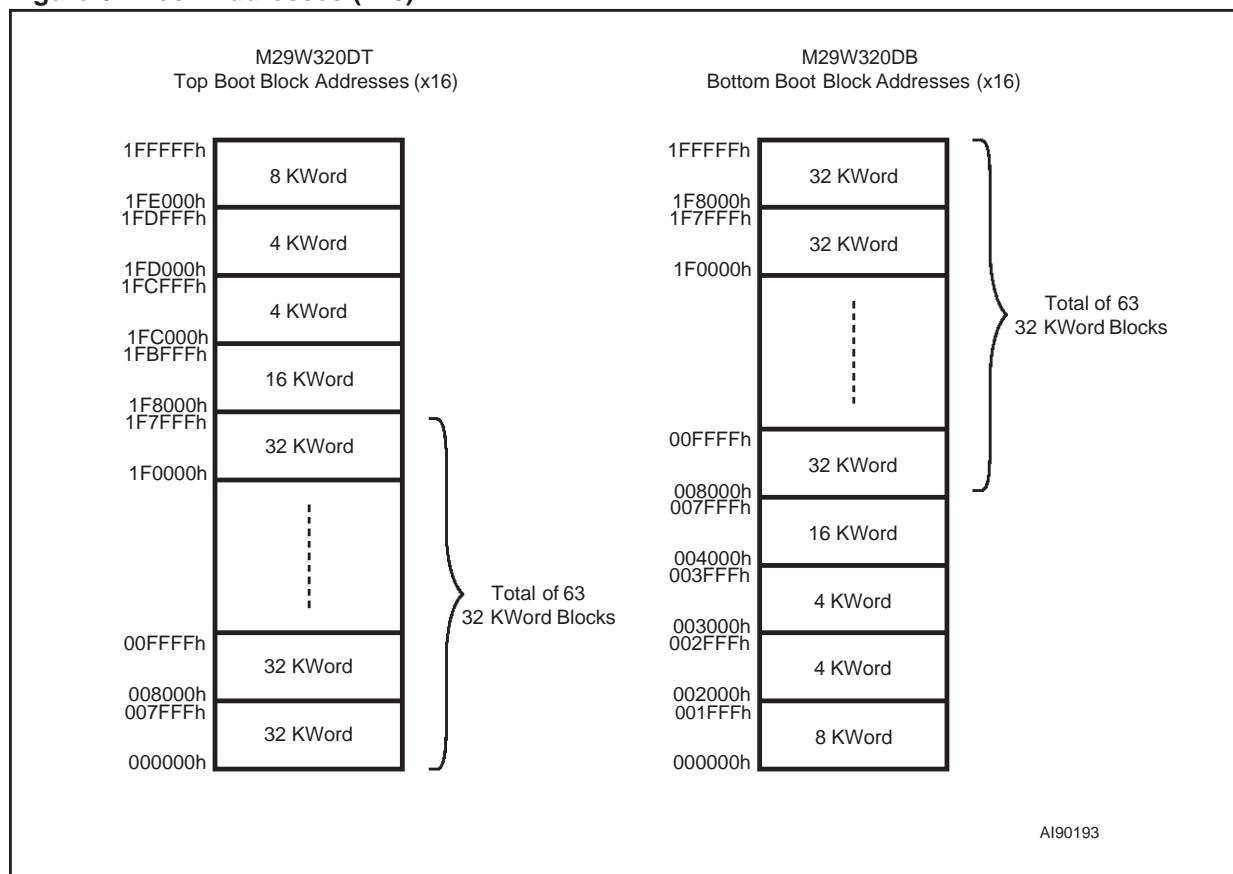
## M29W320DT, M29W320DB

Figure 5. Block Addresses (x8)



Note: Also see Appendix A, Tables 20 and 21 for a full listing of the Block Addresses.

**Figure 6. Block Addresses (x16)**



Note: Also see Appendix A, Tables 20 and 21 for a full listing of the Block Addresses.

### SIGNAL DESCRIPTIONS

See Figure 2, Logic Diagram, and Table 1, Signal Names, for a brief overview of the signals connected to this device.

**Address Inputs (A0-A20).** The Address Inputs select the cells in the memory array to access during Bus Read operations. During Bus Write operations they control the commands sent to the Command Interface of the internal state machine.

**Data Inputs/Outputs (DQ0-DQ7).** The Data I/O outputs the data stored at the selected address during a Bus Read operation. During Bus Write operations they represent the commands sent to the Command Interface of the internal state machine.

**Data Inputs/Outputs (DQ8-DQ14).** The Data I/O outputs the data stored at the selected address during a Bus Read operation when BYTE is High,  $V_{IH}$ . When BYTE is Low,  $V_{IL}$ , these pins are not used and are high impedance. During Bus Write operations the Command Register does not use these bits. When reading the Status Register these bits should be ignored.

**Data Input/Output or Address Input (DQ15A-1).** When BYTE is High,  $V_{IH}$ , this pin behaves as a Data Input/Output pin (as DQ8-DQ14). When BYTE is Low,  $V_{IL}$ , this pin behaves as an address pin; DQ15A-1 Low will select the LSB of the Word on the other addresses, DQ15A-1 High will select the MSB. Throughout the text consider references to the Data Input/Output to include this pin when BYTE is High and references to the Address Inputs to include this pin when BYTE is Low except when stated explicitly otherwise.

**Chip Enable (E).** The Chip Enable,  $\bar{E}$ , activates the memory, allowing Bus Read and Bus Write operations to be performed. When Chip Enable is High,  $V_{IH}$ , all other pins are ignored.

**Output Enable (G).** The Output Enable,  $\bar{G}$ , controls the Bus Read operation of the memory.

**Write Enable (W).** The Write Enable,  $\bar{W}$ , controls the Bus Write operation of the memory's Command Interface.

**Write Protect/V<sub>PP</sub> (V<sub>PP</sub>/WP).** The Write Protect/V<sub>PP</sub> pin provides two functions.

The Write Protect function provides a hardware method of protecting the outermost boot blocks without using  $V_{ID}$ . When V<sub>PP</sub>/WP is at  $V_{IL}$  the device disables program and erase functions in the 16 Kbyte outermost boot blocks, independently of whether these blocks were protected or unprotected using the method described in the Block Protection and Unprotection section.

When V<sub>PP</sub>/WP is at  $V_{IH}$  the device reverts to the previous protection status of the 16 Kbyte boot block. That is, block protection or unprotection for

these blocks depends on whether it was last protected or unprotected using the method described in Block Protection and Unprotection section.

The V<sub>PP</sub> function of the pin provides an optional voltage for fast programming, typically used in a manufacturing environment. When V<sub>PP</sub>/WP is at V<sub>PP</sub> the device automatically enters the Unlock Bypass mode, and uses this higher voltage to reduce the time required for programming operations. When V<sub>PP</sub> is removed from the V<sub>PP</sub>/WP pin, the device returns to normal operation.

Note that the V<sub>PP</sub>/WP pin must not be left floating or unconnected or the device may become unreliable.

**Reset/Block Temporary Unprotect (RP).** The Reset/Block Temporary Unprotect pin can be used to apply a Hardware Reset to the memory or to temporarily unprotect all Blocks that have been protected.

Note that if V<sub>PP</sub>/WP is at  $V_{IL}$ , then the 16 KByte outermost boot block will remain protect even if RP is at  $V_{ID}$ .

A Hardware Reset is achieved by holding Reset/Block Temporary Unprotect Low,  $V_{IL}$ , for at least t<sub>PLPX</sub>. After Reset/Block Temporary Unprotect goes High,  $V_{IH}$ , the memory will be ready for Bus Read and Bus Write operations after t<sub>PHEL</sub> or t<sub>RHEL</sub>, whichever occurs last. See the Ready/Busy Output section, Table 15 and Figure 14, Reset/Temporary Unprotect AC Characteristics for more details.

Holding RP at  $V_{ID}$  will temporarily unprotect the protected Blocks in the memory. Program and Erase operations on all blocks will be possible. The transition from  $V_{IH}$  to  $V_{ID}$  must be slower than t<sub>PHPHH</sub>.

**Ready/Busy Output (RB).** The Ready/Busy pin is an open-drain output that can be used to identify when the memory array can be read. Ready/Busy is high-impedance during Read mode, Auto Select mode and Erase Suspend mode.

Note that if V<sub>PP</sub>/WP is at  $V_{IL}$ , then the 16 KByte outermost boot block will remain protect even if RP is at  $V_{ID}$ .

After a Hardware Reset, Bus Read and Bus Write operations cannot begin until Ready/Busy becomes high-impedance. See Table 15 and Figure 14, Reset/Temporary Unprotect AC Characteristics.

During Program or Erase operations Ready/Busy is Low,  $V_{OL}$ . Ready/Busy will remain Low during Read/Reset commands or Hardware Resets until the memory is ready to enter Read mode.

The use of an open-drain output allows the Ready/Busy pins from several memories to be connected

to a single pull-up resistor. A Low will then indicate that one, or more, of the memories is busy.

**Byte/Word Organization Select (BYTE).** The Byte/Word Organization Select pin is used to switch between the x8 and x16 Bus modes of the memory. When Byte/Word Organization Select is Low,  $V_{IL}$ , the memory is in x8 mode, when it is High,  $V_{IH}$ , the memory is in x16 mode.

**V<sub>CC</sub> Supply Voltage (2.7V to 3.6V).**  $V_{CC}$  provides the power supply for all operations (Read, Program and Erase).

The Command Interface is disabled when the  $V_{CC}$  Supply Voltage is less than the Lockout Voltage,  $V_{LKO}$ . This prevents Bus Write operations from accidentally damaging the data during power up, power down and power surges. If the Program/Erase Controller is programming or erasing during

this time then the operation aborts and the memory contents being altered will be invalid.

A  $0.1\mu F$  capacitor should be connected between the  $V_{CC}$  Supply Voltage pin and the  $V_{SS}$  Ground pin to decouple the current surges from the power supply. The PCB track widths must be sufficient to carry the currents required during program and erase operations,  $I_{CC3}$ .

**$V_{SS}$  Ground.**  $V_{SS}$  is the reference for all voltage measurements.

**Note:** Each device in a system should have  $V_{CC}$  and  $V_{PP}$  decoupled with a  $0.1\mu F$  capacitor close to the pin. See Figure 10, AC Measurement Load Circuit. The PCB trace widths should be sufficient to carry the required  $V_{PP}$  program and erase currents.

## BUS OPERATIONS

There are five standard bus operations that control the device. These are Bus Read, Bus Write, Output Disable, Standby and Automatic Standby. See Tables 2 and 3, Bus Operations, for a summary. Typically glitches of less than 5ns on Chip Enable or Write Enable are ignored by the memory and do not affect bus operations.

**Bus Read.** Bus Read operations read from the memory cells, or specific registers in the Command Interface. A valid Bus Read operation involves setting the desired address on the Address Inputs, applying a Low signal,  $V_{IL}$ , to Chip Enable and Output Enable and keeping Write Enable High,  $V_{IH}$ . The Data Inputs/Outputs will output the value, see Figure 11, Read Mode AC Waveforms, and Table 12, Read AC Characteristics, for details of when the output becomes valid.

**Bus Write.** Bus Write operations write to the Command Interface. A valid Bus Write operation begins by setting the desired address on the Address Inputs. The Address Inputs are latched by the Command Interface on the falling edge of Chip Enable or Write Enable, whichever occurs last. The Data Inputs/Outputs are latched by the Command Interface on the rising edge of Chip Enable or Write Enable, whichever occurs first. Output Enable must remain High,  $V_{IH}$ , during the whole Bus Write operation. See Figures 12 and 13, Write AC Waveforms, and Tables 13 and 14, Write AC Characteristics, for details of the timing requirements.

**Output Disable.** The Data Inputs/Outputs are in the high impedance state when Output Enable is High,  $V_{IH}$ .

**Standby.** When Chip Enable is High,  $V_{IH}$ , the memory enters Standby mode and the Data Inputs/Outputs pins are placed in the high-impedance state. To reduce the Supply Current to the Standby Supply Current,  $I_{CC2}$ , Chip Enable should be held within  $V_{CC} \pm 0.2V$ . For the Standby current level see Table 11, DC Characteristics.

During program or erase operations the memory will continue to use the Program/Erase Supply Current,  $I_{CC3}$ , for Program or Erase operations until the operation completes.

**Automatic Standby.** If CMOS levels ( $V_{CC} \pm 0.2V$ ) are used to drive the bus and the bus is inactive for 300ns or more the memory enters Automatic Standby where the internal Supply Current is reduced to the Standby Supply Current,  $I_{CC2}$ . The Data Inputs/Outputs will still output data if a Bus Read operation is in progress.

### Special Bus Operations

Additional bus operations can be performed to read the Electronic Signature and also to apply and remove Block Protection. These bus operations are intended for use by programming equipment and are not usually used in applications. They require  $V_{ID}$  to be applied to some pins.

**Electronic Signature.** The memory has two codes, the manufacturer code and the device code, that can be read to identify the memory. These codes can be read by applying the signals listed in Tables 2 and 3, Bus Operations.

**Fast Program.** The M29W320D features an optional  $V_{PP}$  voltage supply for fast programming, typically used in a manufacturing environment. When  $V_{PP}/WP$  is at  $V_{PP}$  the device automatically enters the Unlock Bypass mode, and uses this higher voltage to reduce the time required for programming operations. When  $V_{PP}$  is removed from the  $V_{PP}/WP$  pin, the device returns to normal operation. Refer to Tables 2 and 3, Bus Operations.

**Block Protection and Blocks Unprotection.** Each block can be separately protected against accidental Program or Erase. Protected blocks can be unprotected to allow data to be changed.

There are two methods available for protecting and unprotecting the blocks, one for use on programming equipment and the other for in-system use. For further information refer to Application Note AN1122, Applying Protection and Unprotection to M29 Series Flash.

**Table 2. Bus Operations,  $\overline{\text{BYTE}} = \text{V}_{\text{IL}}$** 

Operation	$\overline{\text{E}}$	$\overline{\text{G}}$	$\overline{\text{W}}$	$\text{V}_{\text{PP}}/\overline{\text{WP}}$	Address Inputs DQ15A-1, A0-A20	Data Inputs/Outputs	
						DQ14- DQ8	DQ7-DQ0
Bus Read	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	Cell Address	Hi-Z	Data Output
Bus Write	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	Command Address	Hi-Z	Data Input
Output Disable	X	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	X	Hi-Z	Hi-Z
Standby	$\text{V}_{\text{IH}}$	X	X	$\text{V}_{\text{IH}}$	X	Hi-Z	Hi-Z
Read Manufacturer Code	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	$\text{A}0 = \text{V}_{\text{IL}}, \text{A}1 = \text{V}_{\text{IL}}, \text{A}9 = \text{V}_{\text{ID}}, \text{Others } \text{V}_{\text{IL}} \text{ or } \text{V}_{\text{IH}}$	Hi-Z	20h
Read Device Code	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	$\text{A}0 = \text{V}_{\text{IH}}, \text{A}1 = \text{V}_{\text{IL}}, \text{A}9 = \text{V}_{\text{ID}}, \text{Others } \text{V}_{\text{IL}} \text{ or } \text{V}_{\text{IH}}$	Hi-Z	CAh (M29W320DT) CBh (M29W320DB)
Fast Program	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{PP}}$	Command Address	Hi-Z	Data Input

Note: X =  $\text{V}_{\text{IL}}$  or  $\text{V}_{\text{IH}}$ .

**Table 3. Bus Operations,  $\overline{\text{BYTE}} = \text{V}_{\text{IH}}$** 

Operation	$\overline{\text{E}}$	$\overline{\text{G}}$	$\overline{\text{W}}$	$\text{V}_{\text{PP}}/\overline{\text{WP}}$	Address Inputs A0-A20	Data Inputs/Outputs DQ15A-1, DQ14-DQ0	
Bus Read	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	Cell Address	Data Output	
Bus Write	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	Command Address	Data Input	
Output Disable	X	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	X	Hi-Z	
Standby	$\text{V}_{\text{IH}}$	X	X	$\text{V}_{\text{IH}}$	X	Hi-Z	
Read Manufacturer Code	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	$\text{A}0 = \text{V}_{\text{IL}}, \text{A}1 = \text{V}_{\text{IL}}, \text{A}9 = \text{V}_{\text{ID}}, \text{Others } \text{V}_{\text{IL}} \text{ or } \text{V}_{\text{IH}}$	0020h	
Read Device Code	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IH}}$	$\text{A}0 = \text{V}_{\text{IH}}, \text{A}1 = \text{V}_{\text{IL}}, \text{A}9 = \text{V}_{\text{ID}}, \text{Others } \text{V}_{\text{IL}} \text{ or } \text{V}_{\text{IH}}$	22CAh (M29W320DT) 22CBh (M29W320DB)	
Fast Program	$\text{V}_{\text{IL}}$	$\text{V}_{\text{IH}}$	$\text{V}_{\text{IL}}$	$\text{V}_{\text{PP}}$	Command Address	Data Input	

Note: X =  $\text{V}_{\text{IL}}$  or  $\text{V}_{\text{IH}}$ .

### COMMAND INTERFACE

All Bus Write operations to the memory are interpreted by the Command Interface. Commands consist of one or more sequential Bus Write operations. Failure to observe a valid sequence of Bus Write operations will result in the memory returning to Read mode. The long command sequences are imposed to maximize data security.

The address used for the commands changes depending on whether the memory is in 16-bit or 8-bit mode. See either Table 4, or 5, depending on the configuration that is being used, for a summary of the commands.

**Read/Reset Command.** The Read/Reset command returns the memory to its Read mode where it behaves like a ROM or EPROM, unless otherwise stated. It also resets the errors in the Status Register. Either one or three Bus Write operations can be used to issue the Read/Reset command.

The Read/Reset Command can be issued, between Bus Write cycles before the start of a program or erase operation, to return the device to read mode. Once the program or erase operation has started the Read/Reset command is no longer accepted. The Read/Reset command will be ignored during an Erase Suspend and so it will not resume the Erase operation.

**Auto Select Command.** The Auto Select command is used to read the Manufacturer Code, the Device Code and the Block Protection Status. Three consecutive Bus Write operations are required to issue the Auto Select command. Once the Auto Select command is issued the memory remains in Auto Select mode until a Read/Reset command is issued. Read CFI Query and Read/Reset commands are accepted in Auto Select mode, all other commands are ignored.

From the Auto Select mode the Manufacturer Code can be read using a Bus Read operation with  $A0 = V_{IL}$  and  $A1 = V_{IL}$ . The other address bits may be set to either  $V_{IL}$  or  $V_{IH}$ . The Manufacturer Code for STMicroelectronics is 0020h.

The Device Code can be read using a Bus Read operation with  $A0 = V_{IH}$  and  $A1 = V_{IL}$ . The other address bits may be set to either  $V_{IL}$  or  $V_{IH}$ . The Device Code for the M29W320DT is 22CAh and for the M29W320DB is 22CBh.

The Block Protection Status of each block can be read using a Bus Read operation with  $A0 = V_{IL}$ ,  $A1 = V_{IH}$ , and  $A12-A20$  specifying the address of the block. The other address bits may be set to either  $V_{IL}$  or  $V_{IH}$ . If the addressed block is protected then 01h is output on Data Inputs/Outputs DQ0-DQ7, otherwise 00h is output.

**Program Command.** The Program command can be used to program a value to one address in the memory array at a time. The command re-

quires four Bus Write operations, the final write operation latches the address and data in the internal state machine and starts the Program/Erase Controller.

If the address falls in a protected block then the Program command is ignored, the data remains unchanged. The Status Register is never read and no error condition is given.

During the program operation the memory will ignore all commands. It is not possible to issue any command to abort or pause the operation. Typical program times are given in Table 6. Bus Read operations during the program operation will output the Status Register on the Data Inputs/Outputs. See the section on the Status Register for more details.

After the program operation has completed the memory will return to the Read mode, unless an error has occurred. When an error occurs the memory will continue to output the Status Register. A Read/Reset command must be issued to reset the error condition and return to Read mode.

Note that the Program command cannot change a bit set at '0' back to '1'. One of the Erase Commands must be used to set all the bits in a block or in the whole memory from '0' to '1'.

**Unlock Bypass Command.** The Unlock Bypass command is used in conjunction with the Unlock Bypass Program command to program the memory. When the cycle time to the device is long (as with some EPROM programmers) considerable time saving can be made by using these commands. Three Bus Write operations are required to issue the Unlock Bypass command.

Once the Unlock Bypass command has been issued the memory will only accept the Unlock Bypass Program command and the Unlock Bypass Reset command. The memory can be read as if in Read mode.

The device offers accelerated program operations through the  $V_{PP}/WP$  pin. When the system asserts  $V_{HH}$  on the  $V_{PP}/WP$  pin, the device automatically enters the Unlock Bypass mode. The system may then write the two-cycle Unlock Bypass program command sequence. The device uses the higher voltage on the  $V_{PP}/WP$  pin, to accelerate the operation. Note that the  $V_{PP}/WP$  pin must not be at  $V_{HH}$  for any operation other than accelerated programming or the device may be damaged. In addition, the  $V_{PP}/WP$  pin must not be left floating or unconnected; inconsistent behavior of the device may result.

**Unlock Bypass Program Command.** The Unlock Bypass Program command can be used to program one address in the memory array at a time. The command requires two Bus Write oper-

ations, the final write operation latches the address and data in the internal state machine and starts the Program/Erase Controller.

The Program operation using the Unlock Bypass Program command behaves identically to the Program operation using the Program command. A protected block cannot be programmed; the operation cannot be aborted and the Status Register is read. Errors must be reset using the Read/Reset command, which leaves the device in Unlock Bypass Mode. See the Program command for details on the behavior.

**Unlock Bypass Reset Command.** The Unlock Bypass Reset command can be used to return to Read/Reset mode from Unlock Bypass Mode. Two Bus Write operations are required to issue the Unlock Bypass Reset command. Read/Reset command does not exit from Unlock Bypass Mode.

**Chip Erase Command.** The Chip Erase command can be used to erase the entire chip. Six Bus Write operations are required to issue the Chip Erase Command and start the Program/Erase Controller.

If any blocks are protected then these are ignored and all the other blocks are erased. If all of the blocks are protected the Chip Erase operation appears to start but will terminate within about 100µs, leaving the data unchanged. No error condition is given when protected blocks are ignored.

During the erase operation the memory will ignore all commands, including the Erase Suspend command. It is not possible to issue any command to abort the operation. Typical chip erase times are given in Table 6. All Bus Read operations during the Chip Erase operation will output the Status Register on the Data Inputs/Outputs. See the section on the Status Register for more details.

After the Chip Erase operation has completed the memory will return to the Read Mode, unless an error has occurred. When an error occurs the memory will continue to output the Status Register. A Read/Reset command must be issued to reset the error condition and return to Read Mode.

The Chip Erase Command sets all of the bits in unprotected blocks of the memory to '1'. All previous data is lost.

**Block Erase Command.** The Block Erase command can be used to erase a list of one or more blocks. Six Bus Write operations are required to select the first block in the list. Each additional block in the list can be selected by repeating the sixth Bus Write operation using the address of the

additional block. The Block Erase operation starts the Program/Erase Controller about 50µs after the last Bus Write operation. Once the Program/Erase Controller starts it is not possible to select any more blocks. Each additional block must therefore be selected within 50µs of the last block. The 50µs timer restarts when an additional block is selected. The Status Register can be read after the sixth Bus Write operation. See the Status Register section for details on how to identify if the Program/Erase Controller has started the Block Erase operation. The Block Erase operation can be suspended by using the Erase Suspend command.

If any selected blocks are protected then these are ignored and all the other selected blocks are erased. If all of the selected blocks are protected the Block Erase operation appears to start but will terminate within about 100µs, leaving the data unchanged. No error condition is given when protected blocks are ignored.

During the Block Erase operation the memory will ignore all commands except the Erase Suspend command. Typical block erase times are given in Table 6. All Bus Read operations during the Block Erase operation will output the Status Register on the Data Inputs/Outputs. See the section on the Status Register for more details.

After the Block Erase operation has completed the memory will return to the Read Mode, unless an error has occurred. When an error occurs the memory will continue to output the Status Register. A Read/Reset command must be issued to reset the error condition and return to Read mode.

The Block Erase Command sets all of the bits in the unprotected selected blocks to '1'. All previous data in the selected blocks is lost.

**Erase Suspend Command.** The Erase Suspend Command may be used to temporarily suspend a Block Erase operation and return the memory to Read mode. The command requires one Bus Write operation.

The Program/Erase Controller will suspend within 15µs of the Erase Suspend Command being issued. Once the Program/Erase Controller has stopped the memory will be set to Read mode and the Erase will be suspended. If the Erase Suspend command is issued during the period when the memory is waiting for an additional block (before the Program/Erase Controller starts) then the Erase is suspended immediately and will start immediately when the Erase Resume Command is issued. It is not possible to select any further blocks to erase after the Erase Resume.

During Erase Suspend it is possible to Read and Program cells in blocks that are not being erased; both Read and Program operations behave as normal on these blocks. If any attempt is made to program in a protected block or in the suspended block then the Program command is ignored and the data remains unchanged. The Status Register is not read and no error condition is given. Reading from blocks that are being erased will output the Status Register.

It is also possible to issue the Auto Select, Read CFI Query and Unlock Bypass commands during an Erase Suspend. The Read/Reset command must be issued to return the device to Read Array mode before the Resume command will be accepted.

**Erase Resume Command.** The Erase Resume command must be used to restart the Program/Erase Controller after an Erase Suspend. The de-

vice must be in Read Array mode before the Resume command will be accepted. An erase can be suspended and resumed more than once.

**Read CFI Query Command.** The Read CFI Query Command is used to read data from the Common Flash Interface (CFI) Memory Area. This command is valid when the device is ready to read the array data or when the device is in autoselected mode.

One Bus Write cycle is required to issue the Read CFI Query Command. Once the command is issued subsequent Bus Read operations read from the Common Flash Interface Memory Area. The Read/Reset command must be issued to return the device to Read Array mode. See Appendix B, Tables 22, 23, 24, 25, 26 and 27 for details on the information contained in the Common Flash Interface (CFI) memory area.

Table 4. Commands, 16-bit mode,  $\overline{\text{BYTE}} = \text{V}_{\text{IH}}$ 

Command	Length	Bus Write Operations											
		1st		2nd		3rd		4th		5th		6th	
		Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read/Reset	1	X	F0										
	3	555	AA	2AA	55	X	F0						
Auto Select	3	555	AA	2AA	55	555	90						
Program	4	555	AA	2AA	55	555	A0	PA	PD				
Unlock Bypass	3	555	AA	2AA	55	555	20						
Unlock Bypass Program	2	X	A0	PA	PD								
Unlock Bypass Reset	2	X	90	X	00								
Chip Erase	6	555	AA	2AA	55	555	80	555	AA	2AA	55	555	10
Block Erase	6+	555	AA	2AA	55	555	80	555	AA	2AA	55	BA	30
Erase Suspend	1	X	B0										
Erase Resume	1	X	30										
Read CFI Query	1	55	98										

Note: X Don't Care, PA Program Address, PD Program Data, BA Any address in the Block. All values in the table are in hexadecimal.

The Command Interface only uses A-1, A0-A10 and DQ0-DQ7 to verify the commands; A11-A20, DQ8-DQ14 and DQ15 are Don't Care. DQ15A-1 is A-1 when BYTE is  $\text{V}_{\text{IL}}$  or DQ15 when BYTE is  $\text{V}_{\text{IH}}$ .

**Read/Reset.** After a Read/Reset command, read the memory as normal until another command is issued. Read/Reset command is ignored during algorithm execution.

**Auto Select.** After an Auto Select command, read Manufacturer ID, Device ID or Block Protection Status.

**Program, Unlock Bypass Program, Chip Erase, Block Erase.** After these commands read the Status Register until the Program/Erase Controller completes and the memory returns to Read Mode. Add additional Blocks during Block Erase Command with additional Bus Write Operations until Timeout Bit is set.

**Unlock Bypass.** After the Unlock Bypass command issue Unlock Bypass Program or Unlock Bypass Reset commands.

**Unlock Bypass Reset.** After the Unlock Bypass Reset command read the memory as normal until another command is issued.

**Erase Suspend.** After the Erase Suspend command read non-erasing memory blocks as normal, issue Auto Select and Program commands on non-erasing blocks as normal.

**Erase Resume.** After the Erase Resume command the suspended Erase operation resumes, read the Status Register until the Program/Erase Controller completes and the memory returns to Read Mode.

**CFI Query.** Command is valid when device is ready to read array data or when device is in autoselected mode.

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**Table 5. Commands, 8-bit mode,  $\overline{\text{BYTE}} = \text{V}_{\text{IL}}$**

Command	Length	Bus Write Operations											
		1st		2nd		3rd		4th		5th		6th	
		Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read/Reset	1	X	F0										
	3	AAA	AA	555	55	X	F0						
Auto Select	3	AAA	AA	555	55	AAA	90						
Program	4	AAA	AA	555	55	AAA	A0	PA	PD				
Unlock Bypass	3	AAA	AA	555	55	AAA	20						
Unlock Bypass Program	2	X	A0	PA	PD								
Unlock Bypass Reset	2	X	90	X	00								
Chip Erase	6	AAA	AA	555	55	AAA	80	AAA	AA	555	55	AAA	10
Block Erase	6+	AAA	AA	555	55	AAA	80	AAA	AA	555	55	BA	30
Erase Suspend	1	X	B0										
Erase Resume	1	X	30										
Read CFI Query	1	AA	98										

Note: X Don't Care, PA Program Address, PD Program Data, BA Any address in the Block. All values in the table are in hexadecimal.

The Command Interface only uses A<sub>1</sub>-A<sub>10</sub> and DQ0-DQ7 to verify the commands; A11-A20, DQ8-DQ14 and DQ15 are Don't Care. DQ15A<sub>1</sub> is A<sub>1</sub> when  $\overline{\text{BYTE}}$  is  $\text{V}_{\text{IL}}$  or DQ15 when  $\overline{\text{BYTE}}$  is  $\text{V}_{\text{IH}}$ .

**Read/Reset.** After a Read/Reset command, read the memory as normal until another command is issued. Read/Reset command is ignored during algorithm execution.

**Auto Select.** After an Auto Select command, read Manufacturer ID, Device ID or Block Protection Status.

**Program, Unlock Bypass Program, Chip Erase, Block Erase.** After these commands read the Status Register until the Program/Erase Controller completes and the memory returns to Read Mode. Add additional Blocks during Block Erase Command with additional Bus Write Operations until Timeout Bit is set.

**Unlock Bypass.** After the Unlock Bypass command issue Unlock Bypass Program or Unlock Bypass Reset commands.

**Unlock Bypass Reset.** After the Unlock Bypass Reset command read the memory as normal until another command is issued.

**Erase Suspend.** After the Erase Suspend command read non-erasing memory blocks as normal, issue Auto Select and Program commands on non-erasing blocks as normal.

**Erase Resume.** After the Erase Resume command the suspended Erase operation resumes, read the Status Register until the Program/Erase Controller completes and the memory returns to Read Mode.

**CFI Query.** Command is valid when device is ready to read array data or when device is in autoselected mode.

**Table 6. Program, Erase Times and Program, Erase Endurance Cycles**

Parameter	Min	Typ <sup>(1)</sup>	Typical after 100k W/E Cycles <sup>(1)</sup>	Max	Unit
Chip Erase		40	40	200	s
Block Erase (64 KBytes)		0.8		6	s
Program (Byte or Word)		10		200	μs
Accelerated Program (Byte or Word)		8		150	μs
Chip Program (Byte by Byte)		40		200	s
Chip Program (Word by Word)		20		100	s
Program/Erase Cycles (per Block)	100,000				cycles

Note: 1.  $T_A = 25^\circ\text{C}$ ,  $V_{\text{CC}} = 3.3\text{V}$ .

## STATUS REGISTER

Bus Read operations from any address always read the Status Register during Program and Erase operations. It is also read during Erase Suspend when an address within a block being erased is accessed.

The bits in the Status Register are summarized in Table 7, Status Register Bits.

**Data Polling Bit (DQ7).** The Data Polling Bit can be used to identify whether the Program/Erase Controller has successfully completed its operation or if it has responded to an Erase Suspend. The Data Polling Bit is output on DQ7 when the Status Register is read.

During Program operations the Data Polling Bit outputs the complement of the bit being programmed to DQ7. After successful completion of the Program operation the memory returns to Read mode and Bus Read operations from the address just programmed output DQ7, not its complement.

During Erase operations the Data Polling Bit outputs '0', the complement of the erased state of DQ7. After successful completion of the Erase operation the memory returns to Read Mode.

In Erase Suspend mode the Data Polling Bit will output a '1' during a Bus Read operation within a block being erased. The Data Polling Bit will change from a '0' to a '1' when the Program/Erase Controller has suspended the Erase operation.

Figure 7, Data Polling Flowchart, gives an example of how to use the Data Polling Bit. A Valid Address is the address being programmed or an address within the block being erased.

**Toggle Bit (DQ6).** The Toggle Bit can be used to identify whether the Program/Erase Controller has successfully completed its operation or if it has responded to an Erase Suspend. The Toggle Bit is output on DQ6 when the Status Register is read.

During Program and Erase operations the Toggle Bit changes from '0' to '1' to '0', etc., with successive Bus Read operations at any address. After successful completion of the operation the memory returns to Read mode.

During Erase Suspend mode the Toggle Bit will output when addressing a cell within a block being erased. The Toggle Bit will stop toggling when the Program/Erase Controller has suspended the Erase operation.

If any attempt is made to erase a protected block, the operation is aborted, no error is signalled and DQ6 toggles for approximately 100 $\mu$ s. If any attempt is made to program a protected block or a suspended block, the operation is aborted, no er-

ror is signalled and DQ6 toggles for approximately 1 $\mu$ s.

Figure 8, Data Toggle Flowchart, gives an example of how to use the Data Toggle Bit.

**Error Bit (DQ5).** The Error Bit can be used to identify errors detected by the Program/Erase Controller. The Error Bit is set to '1' when a Program, Block Erase or Chip Erase operation fails to write the correct data to the memory. If the Error Bit is set a Read/Reset command must be issued before other commands are issued. The Error bit is output on DQ5 when the Status Register is read.

Note that the Program command cannot change a bit set to '0' back to '1' and attempting to do so will set DQ5 to '1'. A Bus Read operation to that address will show the bit is still '0'. One of the Erase commands must be used to set all the bits in a block or in the whole memory from '0' to '1'.

**Erase Timer Bit (DQ3).** The Erase Timer Bit can be used to identify the start of Program/Erase Controller operation during a Block Erase command. Once the Program/Erase Controller starts erasing the Erase Timer Bit is set to '1'. Before the Program/Erase Controller starts the Erase Timer Bit is set to '0' and additional blocks to be erased may be written to the Command Interface. The Erase Timer Bit is output on DQ3 when the Status Register is read.

**Alternative Toggle Bit (DQ2).** The Alternative Toggle Bit can be used to monitor the Program/Erase controller during Erase operations. The Alternative Toggle Bit is output on DQ2 when the Status Register is read.

During Chip Erase and Block Erase operations the Toggle Bit changes from '0' to '1' to '0', etc., with successive Bus Read operations from addresses within the blocks being erased. A protected block is treated the same as a block not being erased. Once the operation completes the memory returns to Read mode.

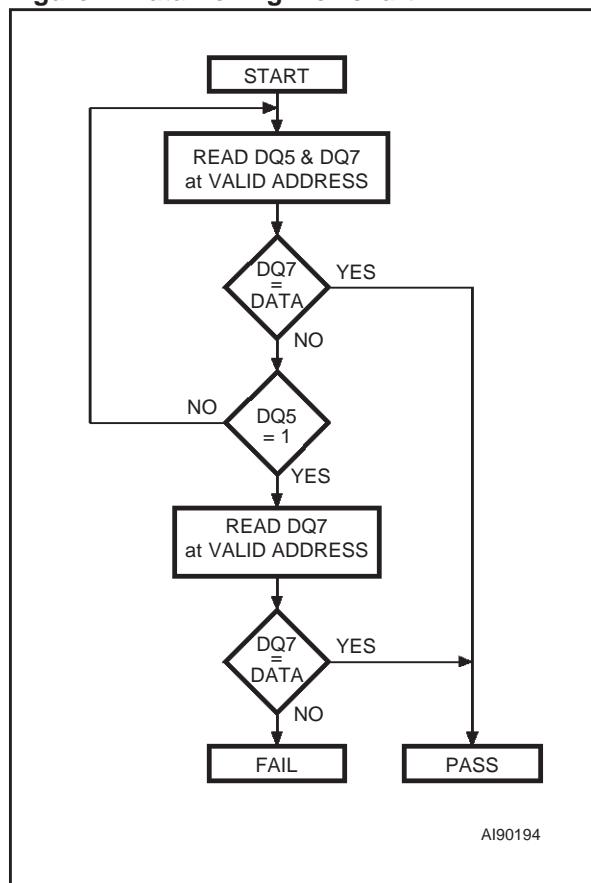
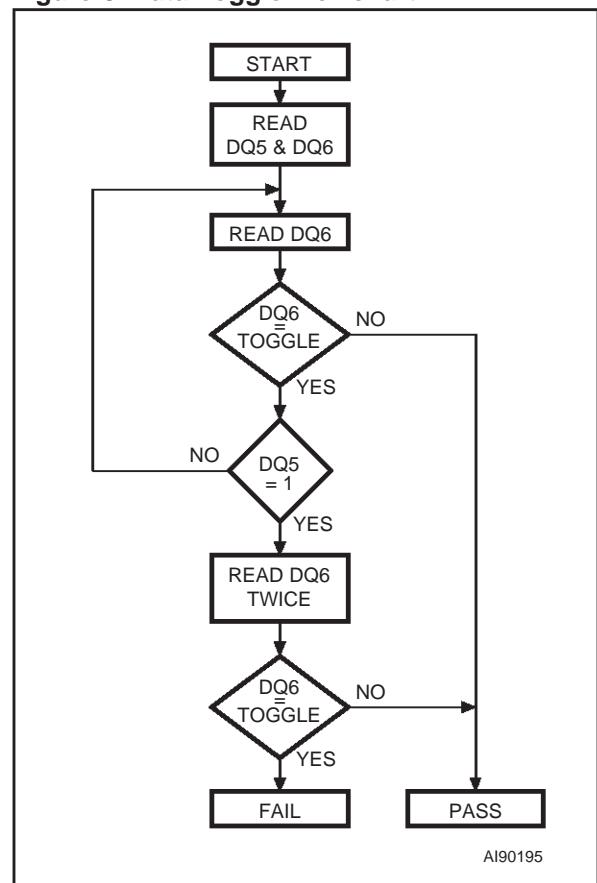
During Erase Suspend the Alternative Toggle Bit changes from '0' to '1' to '0', etc. with successive Bus Read operations from addresses within the blocks being erased. Bus Read operations to addresses within blocks not being erased will output the memory cell data as if in Read mode.

After an Erase operation that causes the Error Bit to be set the Alternative Toggle Bit can be used to identify which block or blocks have caused the error. The Alternative Toggle Bit changes from '0' to '1' to '0', etc. with successive Bus Read Operations from addresses within blocks that have not erased correctly. The Alternative Toggle Bit does not change if the addressed block has erased correctly.

**Table 7. Status Register Bits**

Operation	Address	DQ7	DQ6	DQ5	DQ3	DQ2	$R\bar{B}$
Program	Any Address	$\overline{DQ7}$	Toggle	0	–	–	0
Program During Erase Suspend	Any Address	$\overline{DQ7}$	Toggle	0	–	–	0
Program Error	Any Address	$\overline{DQ7}$	Toggle	1	–	–	0
Chip Erase	Any Address	0	Toggle	0	1	Toggle	0
Block Erase before timeout	Erasing Block	0	Toggle	0	0	Toggle	0
	Non-Erasing Block	0	Toggle	0	0	No Toggle	0
Block Erase	Erasing Block	0	Toggle	0	1	Toggle	0
	Non-Erasing Block	0	Toggle	0	1	No Toggle	0
Erase Suspend	Erasing Block	1	No Toggle	0	–	Toggle	1
	Non-Erasing Block					Data read as normal	1
Erase Error	Good Block Address	0	Toggle	1	1	No Toggle	0
	Faulty Block Address	0	Toggle	1	1	Toggle	0

Note: Unspecified data bits should be ignored.

**Figure 7. Data Polling Flowchart**

**Figure 8. Data Toggle Flowchart**


**MAXIMUM RATING**

Stressing the device above the rating listed in the Absolute Maximum Ratings table may cause permanent damage to the device. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. These are stress ratings only and operation of the device at

these or any other conditions above those indicated in the Operating sections of this specification is not implied. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

**Table 8. Absolute Maximum Ratings**

Symbol	Parameter	Min	Max	Unit
T <sub>BIAS</sub>	Temperature Under Bias	-50	125	°C
T <sub>STG</sub>	Storage Temperature	-65	150	°C
V <sub>IO</sub>	Input or Output Voltage <sup>(1,2)</sup>	-0.6	V <sub>CC</sub> +0.6	V
V <sub>CC</sub>	Supply Voltage	-0.6	4	V
V <sub>ID</sub>	Identification Voltage	-0.6	13.5	V
V <sub>PP</sub>	Program Voltage	-0.6	13.5	V

Note: 1. Minimum voltage may undershoot to -2V during transition and for less than 20ns during transitions.

2. Maximum voltage may overshoot to V<sub>CC</sub> +2V during transition and for less than 20ns during transitions.

## M29W320DT, M29W320DB

### DC AND AC PARAMETERS

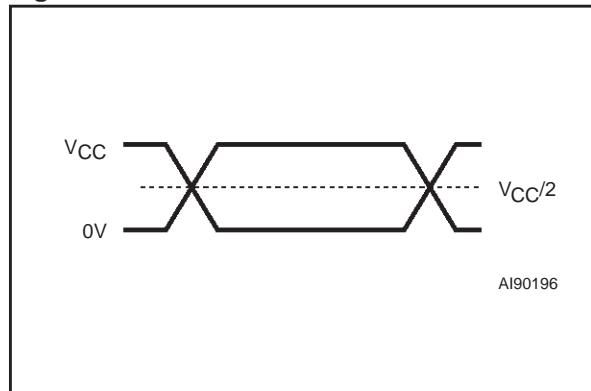
This section summarizes the operating measurement conditions, and the DC and AC characteristics of the device. The parameters in the DC and AC characteristics Tables that follow, are derived from tests performed under the Measurement

Conditions summarized in Table 9, Operating and AC Measurement Conditions. Designers should check that the operating conditions in their circuit match the operating conditions when relying on the quoted parameters.

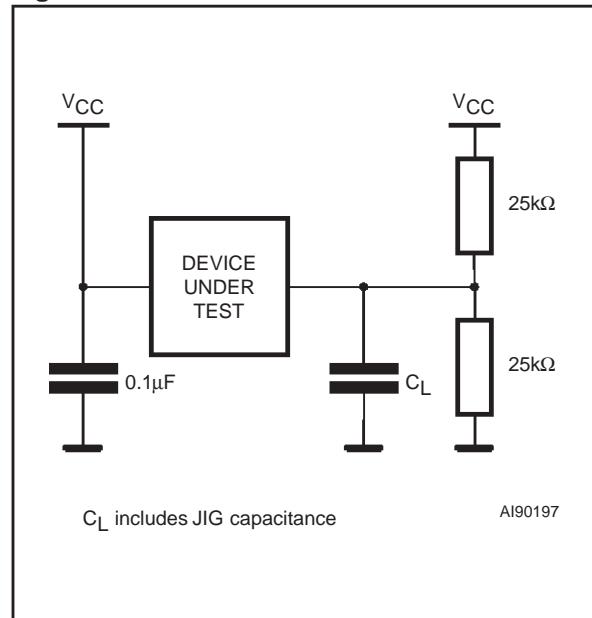
**Table 9. Operating and AC Measurement Conditions**

Parameter	M29W320D				Unit	
	70		90			
	Min	Max	Min	Max		
V <sub>CC</sub> Supply Voltage	3.0	3.6	2.7	3.6	V	
Ambient Operating Temperature	-40	85	-40	85	°C	
Load Capacitance (C <sub>L</sub> )	30		30		pF	
Input Rise and Fall Times	10		10		ns	
Input Pulse Voltages	0 to V <sub>CC</sub>		0 to V <sub>CC</sub>		V	
Input and Output Timing Ref. Voltages	V <sub>CC</sub> /2		V <sub>CC</sub> /2		V	

**Figure 9. AC Measurement I/O Waveform**



**Figure 10. AC Measurement Load Circuit**



**Table 10. Device Capacitance**

Symbol	Parameter	Test Condition	Min	Max	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V		6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V		12	pF

Note: Sampled only, not 100% tested.

**Table 11. DC Characteristics**

Symbol	Parameter	Test Condition	Min	Max	Unit
$I_{LI}$	Input Leakage Current	$0V \leq V_{IN} \leq V_{CC}$		$\pm 1$	$\mu A$
$I_{LO}$	Output Leakage Current	$0V \leq V_{OUT} \leq V_{CC}$		$\pm 1$	$\mu A$
$I_{CC1}$	Supply Current (Read)	$\bar{E} = V_{IL}, \bar{G} = V_{IH}, f = 6MHz$		10	mA
$I_{CC2}$	Supply Current (Standby)	$\bar{E} = V_{CC} \pm 0.2V, \bar{RP} = V_{CC} \pm 0.2V$		100	$\mu A$
$I_{CC3}^{(1)}$	Supply Current (Program/Erase)	Program/Erase Controller active		20	mA
$V_{IL}$	Input Low Voltage		-0.5	0.8	V
$V_{IH}$	Input High Voltage		$0.7V_{CC}$	$V_{CC} + 0.3$	V
$V_{PP}$	Voltage for $V_{PP}/\bar{V}_{WP}$ Block Protect/Unprotect and Program Acceleration	$V_{CC} = 3.0V \pm 10\%$	11.5	12.5	V
$V_{OL}$	Output Low Voltage	$I_{OL} = 1.8mA$		0.45	V
$V_{OH}$	Output High Voltage	$I_{OH} = -100\mu A$	$V_{CC} - 0.4$		V
$V_{ID}$	Identification Voltage		11.5	12.5	V
$I_{ID}$	Identification Current	$A9 = V_{ID}$		100	$\mu A$
$V_{LKO}$	Program/Erase Lockout Supply Voltage		1.8	2.3	V

Note: 1. Sampled only, not 100% tested.

## M29W320DT, M29W320DB

Figure 11. Read Mode AC Waveforms

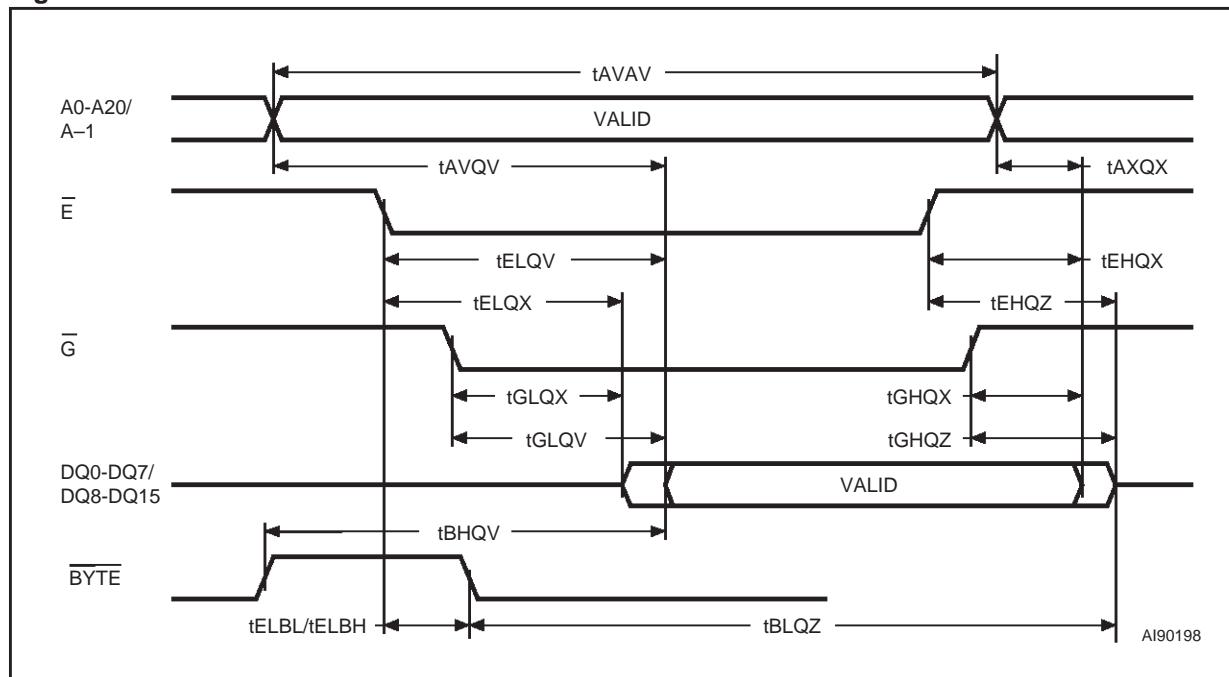


Table 12. Read AC Characteristics

Symbol	Alt	Parameter	Test Condition		M29W320D		Unit
			70	90	70	90	
tAVAV	tRC	Address Valid to Next Address Valid	$\overline{E} = V_{IL}$ , $G = V_{IL}$	Min	70	90	ns
tAVQV	tACC	Address Valid to Output Valid	$\overline{E} = V_{IL}$ , $G = V_{IL}$	Max	70	90	ns
tELQX <sup>(1)</sup>	tLZ	Chip Enable Low to Output Transition	$\overline{G} = V_{IL}$	Min	0	0	ns
tELQV	tCE	Chip Enable Low to Output Valid	$\overline{G} = V_{IL}$	Max	70	90	ns
tGLQX <sup>(1)</sup>	tOLZ	Output Enable Low to Output Transition	$\overline{E} = V_{IL}$	Min	0	0	ns
tGLQV	tOE	Output Enable Low to Output Valid	$\overline{E} = V_{IL}$	Max	30	35	ns
tEHQZ <sup>(1)</sup>	tHZ	Chip Enable High to Output Hi-Z	$\overline{G} = V_{IL}$	Max	25	30	ns
tGHQZ <sup>(1)</sup>	tDF	Output Enable High to Output Hi-Z	$\overline{E} = V_{IL}$	Max	25	30	ns
tEHQX tGHQX tAXQX	tOH	Chip Enable, Output Enable or Address Transition to Output Transition		Min	0	0	ns
tELBL tELBH	tELFL tELFH	Chip Enable to $\overline{BYTE}$ Low or High		Max	5	5	ns
tBLQZ	tFLQZ	$\overline{BYTE}$ Low to Output Hi-Z		Max	25	30	ns
tBHQV	tFHQV	$\overline{BYTE}$ High to Output Valid		Max	30	40	ns

Note: 1. Sampled only, not 100% tested.

Figure 12. Write AC Waveforms, Write Enable Controlled

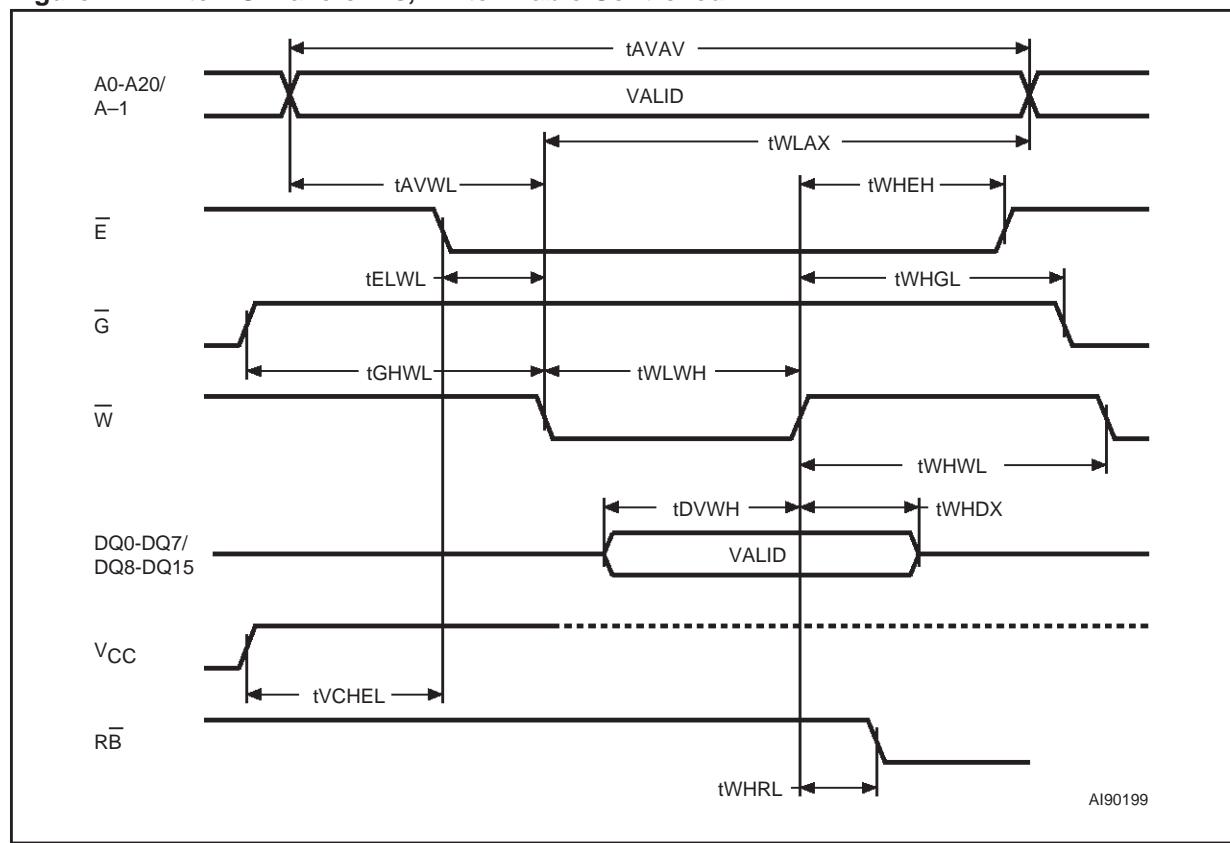


Table 13. Write AC Characteristics, Write Enable Controlled

Symbol	Alt	Parameter	M29W320D		Unit
			70	90	
tAVAV	tWC	Address Valid to Next Address Valid	Min	70	90
tELWL	tCS	Chip Enable Low to Write Enable Low	Min	0	0
tWLWH	tWP	Write Enable Low to Write Enable High	Min	45	50
tDVWH	tDS	Input Valid to Write Enable High	Min	45	50
tWHDX	tDH	Write Enable High to Input Transition	Min	0	0
tWHEH	tCH	Write Enable High to Chip Enable High	Min	0	0
tWHWL	tWPH	Write Enable High to Write Enable Low	Min	30	30
tAVWL	tAS	Address Valid to Write Enable Low	Min	0	0
tWLAX	tAH	Write Enable Low to Address Transition	Min	45	50
tGHWL		Output Enable High to Write Enable Low	Min	0	0
tWHGL	tOEH	Write Enable High to Output Enable Low	Min	0	0
tWHRL <sup>(1)</sup>	tBUSY	Program/Erase Valid to RB Low	Max	30	35
tVCHL	tVCS	Vcc High to Chip Enable Low	Min	50	50
					μs

Note: 1. Sampled only, not 100% tested.

## M29W320DT, M29W320DB

Figure 13. Write AC Waveforms, Chip Enable Controlled

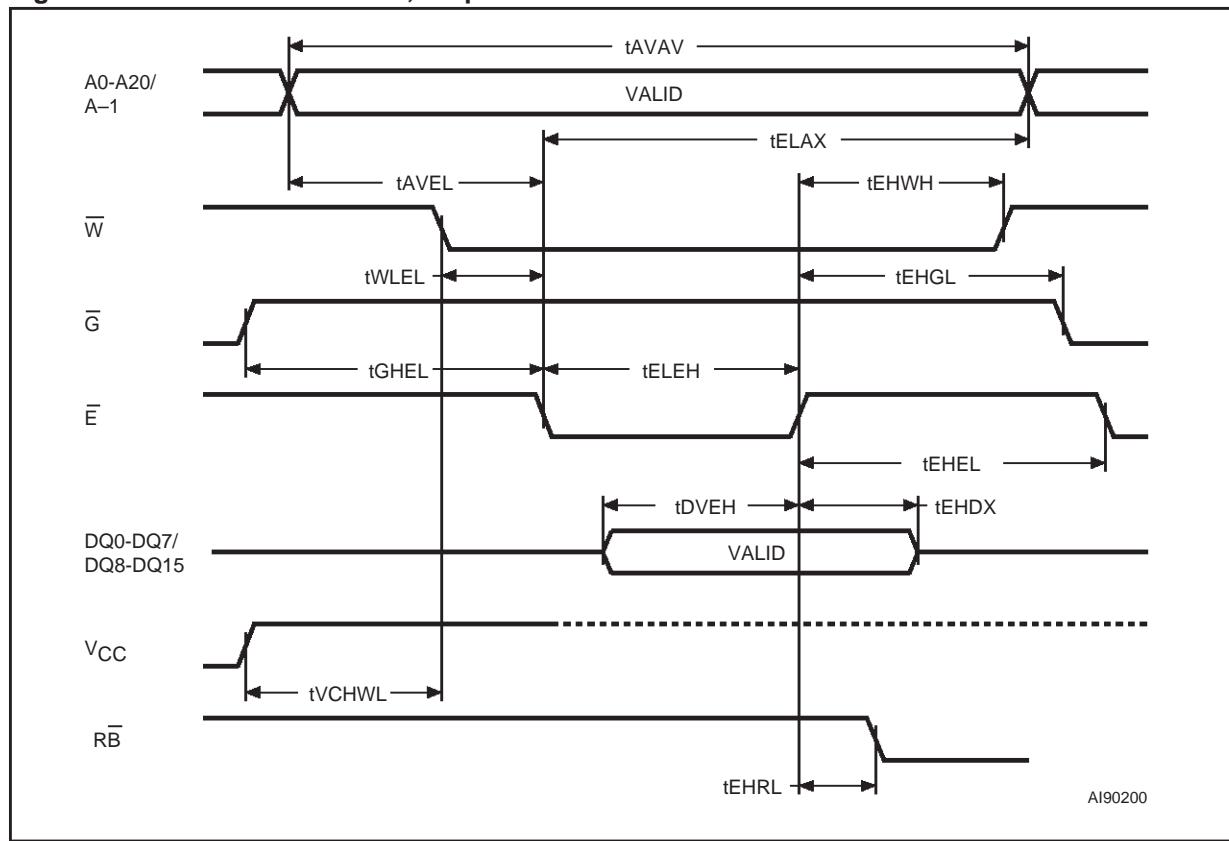


Table 14. Write AC Characteristics, Chip Enable Controlled

Symbol	Alt	Parameter	M29W320D		Unit
			70	90	
tAVAV	tWC	Address Valid to Next Address Valid	Min	70	90
tWEL	tWS	Write Enable Low to Chip Enable Low	Min	0	0
tELEH	tCP	Chip Enable Low to Chip Enable High	Min	45	50
tDVEH	tDS	Input Valid to Chip Enable High	Min	45	50
tEHDX	tDH	Chip Enable High to Input Transition	Min	0	0
tEHWL	tWH	Chip Enable High to Write Enable High	Min	0	0
tEHEL	tCPH	Chip Enable High to Chip Enable Low	Min	30	30
tAVEL	tAS	Address Valid to Chip Enable Low	Min	0	0
tELAX	tAH	Chip Enable Low to Address Transition	Min	45	50
tGHEL		Output Enable High Chip Enable Low	Min	0	0
tEHGL	tOEH	Chip Enable High to Output Enable Low	Min	0	0
tEHRL <sup>(1)</sup>	tBUSY	Program/Erase Valid to RB Low	Max	30	35
tVCHWL	tVCS	Vcc High to Write Enable Low	Min	50	50

Note: 1. Sampled only, not 100% tested.

Figure 14. Reset/Block Temporary Unprotect AC Waveforms

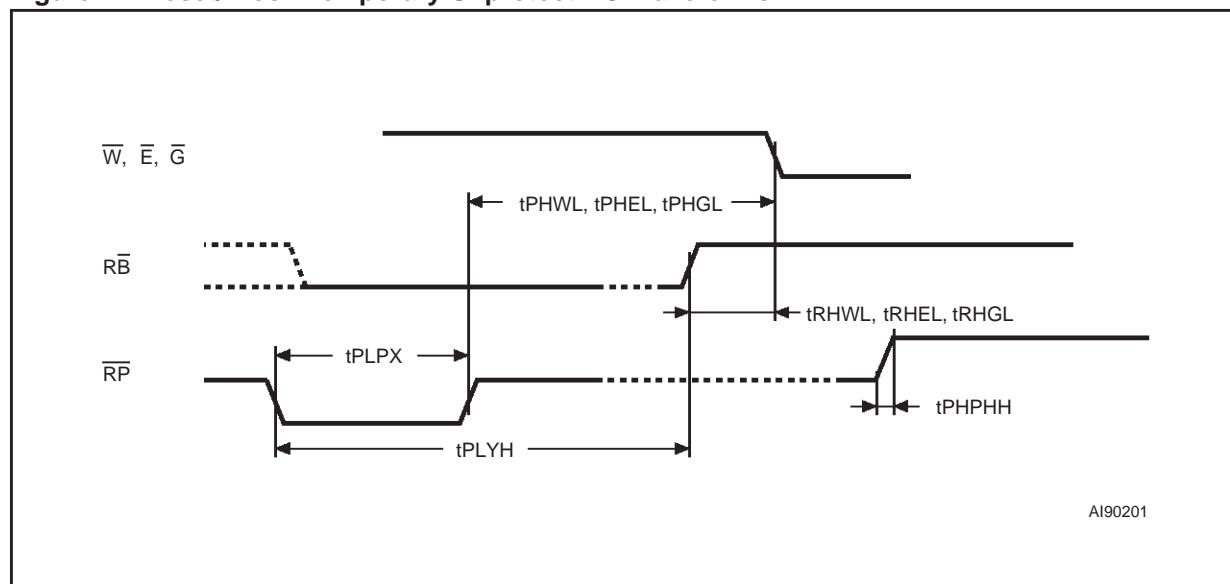
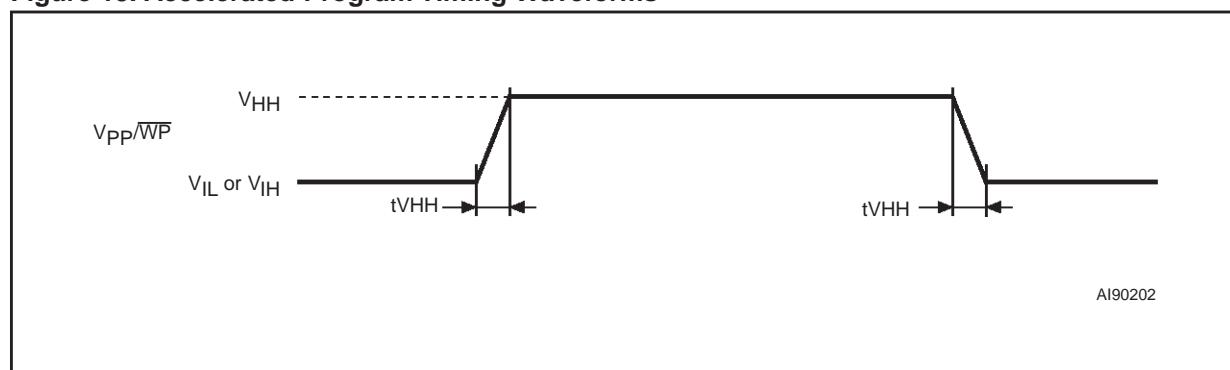


Table 15. Reset/Block Temporary Unprotect AC Characteristics

Symbol	Alt	Parameter	M29W320D		Unit
			70	90	
tPHWL <sup>(1)</sup> tPHEL tPHGL <sup>(1)</sup>	t <sub>RH</sub>	RP High to Write Enable Low, Chip Enable Low, Output Enable Low	Min	50	50 ns
tRHWL <sup>(1)</sup> tRHEL <sup>(1)</sup> tRHGL <sup>(1)</sup>	t <sub>RB</sub>	RB High to Write Enable Low, Chip Enable Low, Output Enable Low	Min	0	0 ns
tPLPX	t <sub>RP</sub>	RP Pulse Width	Min	500	500 ns
tPLYH <sup>(1)</sup>	t <sub>READY</sub>	RP Low to Read Mode	Max	10	10 $\mu$ s
tPHPHH <sup>(1)</sup>	t <sub>VIDR</sub>	RP Rise Time to V <sub>ID</sub>	Min	500	500 ns
tVHH <sup>(1)</sup>		V <sub>HH</sub> Rise and Fall Time	Min	250	250 ns

Note: 1. Sampled only, not 100% tested.

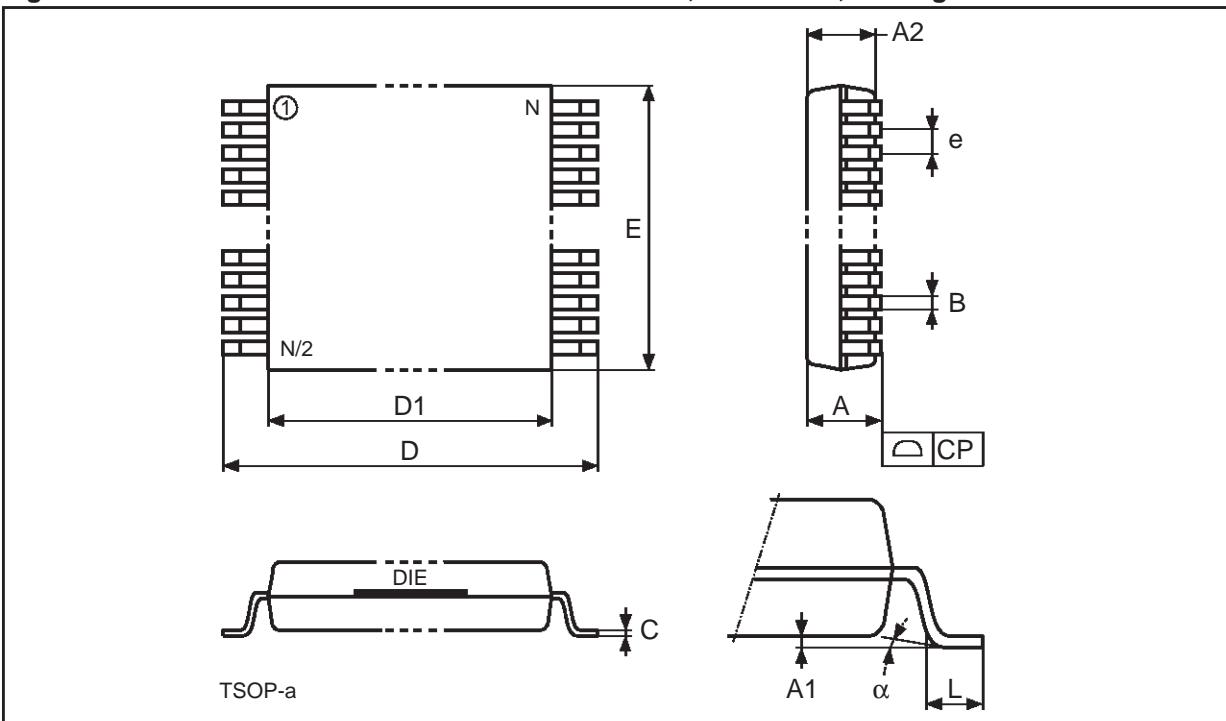
Figure 15. Accelerated Program Timing Waveforms



## M29W320DT, M29W320DB

### PACKAGE MECHANICAL

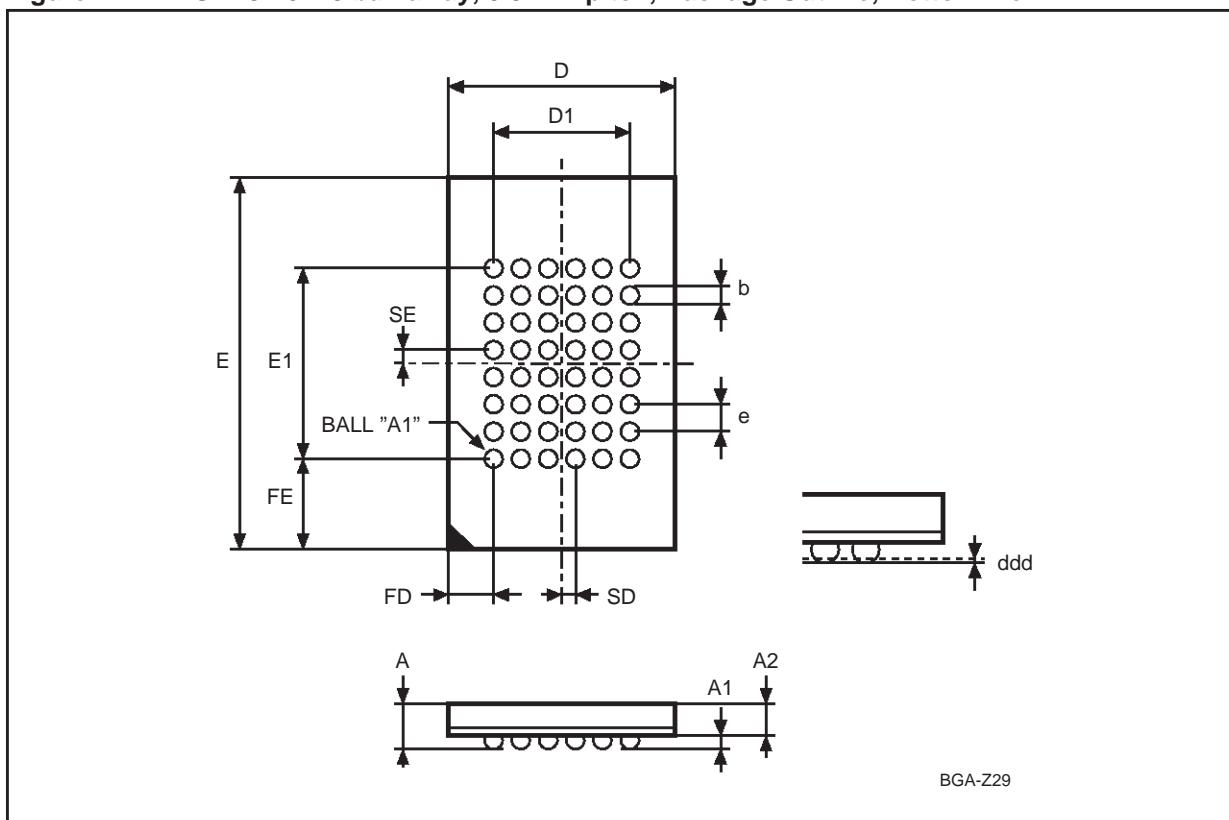
Figure 16. TSOP48 - 48 lead Plastic Thin Small Outline, 12 x 20mm, Package Outline



Note: Drawing is not to scale.

Table 16. TSOP48 - 48 lead Plastic Thin Small Outline, 12 x 20mm, Package Mechanical Data

Symbol	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A			1.20			0.0472
A1		0.05	0.15		0.0020	0.0059
A2		0.95	1.05		0.0374	0.0413
B		0.17	0.27		0.0067	0.0106
C		0.10	0.21		0.0039	0.0083
D		19.80	20.20		0.7795	0.7953
D1		18.30	18.50		0.7205	0.7283
E		11.90	12.10		0.4685	0.4764
e	0.50	—	—	0.0197	—	—
L		0.50	0.70		0.0197	0.0279
α		0°	5°		0°	5°
N	48			48		
CP			0.10			0.0039

**Figure 17. TFBGA48 - 6 x 8 ball array, 0.8 mm pitch, Package Outline, Bottom view**


Note: Drawing is not to scale.

**Table 17. TFBGA48 - 6 x 8 ball array, 0.8 mm pitch, Package Mechanical Data**

Symbol	millimeters			inches		
	Typ	Min	Max	Typ	Min	Max
A			1.200			0.0472
A1		0.250			0.0098	
A2			0.900			0.0354
b		0.350	0.450		0.0138	0.0177
D	6.000	5.900	6.400	0.2362	0.2323	0.2520
D1	4.000	—	—	0.1575	—	—
ddd			0.100			0.0039
E	11.000	10.900	11.100	0.4331	0.4291	0.4370
E1	5.600	—	—	0.2205	—	—
e	0.800	—	—	0.0315	—	—
FD	1.000	—	—	0.0394	—	—
FE	2.700	—	—	0.1063	—	—
SD	0.400	—	—	0.0157	—	—
SE	0.400	—	—	0.0157	—	—

## **M29W320DT, M29W320DB**

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### **PART NUMBERING**

**Table 18. Ordering Information Scheme**

Example:

**Device Type**

M29

**Operating Voltage**

W =  $V_{CC}$  = 2.7 to 3.6V

**Device Function**

320D = 32 Mbit (x8/x16), Boot Block

**Array Matrix**

T = Top Boot

B = Bottom Boot

**Speed**

70 = 70 ns

90 = 90 ns

**Package**

N = TSOP48: 12 x 20 mm

ZA = TFBGA48: 0.80 mm pitch

**Temperature Range**

1 = 0 to 70 °C

6 = -40 to 85 °C

**Option**

T = Tape & Reel Packing

Devices are shipped from the factory with the memory content bits erased to '1'.

For a list of available options (Speed, Package, etc...) or for further information on any aspect of this device, please contact the ST Sales Office nearest to you.

**REVISION HISTORY****Table 19. Document Revision History**

Date	Version	Revision Details
March-2001	-01	First Issue (Brief Data)
08-Jun-2001	-02	Document expanded to full Product Preview
22-Jun-2001	-03	Minor text corrections to Read/Reset and Read CFI commands and Status Register Error and Toggle Bits.
27-Jul-2001	-04	Document type: from Product Preview to Preliminary Data TFBGA connections and Block Addresses (x16) diagrams clarification Write Protect and Block Unprotect clarification CFI Primary Algorithm table, Block Protection change

**APPENDIX A. BLOCK ADDRESS TABLE**
**Table 20. Top Boot Block Addresses,  
M29W320DT**

#	Size (KByte/ KWord)	Address Range (x8)	Address Range (x16)
66	16/8	3FC000h-3FFFFFh	1FE000h-1FFFFFh
65	8/4	3FA000h-3FBFFFh	1FD000h-1FDFFFh
64	8/4	3F8000h-3F9FFFh	1FC000h-1FCFFFh
63	32/16	3F0000h-3F7FFFh	1F8000h-1FBFFFh
62	64/32	3E0000h-3EFFFFh	1F0000h-1F7FFFh
61	64/32	3D0000h-3DFFFFh	1E8000h-1EFFFFFh
60	64/32	3C0000h-3CFFFFh	1E0000h-1E7FFFh
59	64/32	3B0000h-3BFFFFh	1D8000h-1DFFFFh
58	64/32	3A0000h-3AFFFFh	1D0000h-1D7FFFh
57	64/32	390000h-39FFFFh	1C8000h-1CFFFFh
56	64/32	380000h-18FFFFh	1C0000h-1C7FFFh
55	64/32	370000h-37FFFFh	1B8000h-1BFFFFh
54	64/32	360000h-36FFFFh	1B0000h-1B7FFFh
53	64/32	350000h-35FFFFh	1A8000h-1AFFFFFh
52	64/32	340000h-34FFFFh	1A0000h-1A7FFFh
51	64/32	330000h-33FFFFh	198000h-19FFFFh
50	64/32	320000h-32FFFFh	190000h-197FFFh
49	64/32	310000h-31FFFFh	188000h-18FFFFh
48	64/32	300000h-30FFFFh	180000h-187FFFh
47	64/32	2F0000h-2FFFFFFh	178000h-17FFFFh
46	64/32	2E0000h-2EFFFFh	170000h-177FFFh
45	64/32	2D0000h-2DFFFFh	168000h-16FFFFh
44	64/32	2C0000h-2CFFFFh	160000h-167FFFh
43	64/32	2B0000h-2BFFFFh	158000h-15FFFFh
42	64/32	2A0000h-2AFFFFh	150000h-157FFFh
41	64/32	290000h-29FFFFh	148000h-14FFFFh
40	64/32	280000h-28FFFFh	140000h-147FFFh
39	64/32	270000h-27FFFFh	138000h-13FFFFh
38	64/32	260000h-26FFFFh	130000h-137FFFh
37	64/32	250000h-25FFFFh	128000h-12FFFFh
36	64/32	240000h-24FFFFh	120000h-127FFFh
35	64/32	230000h-23FFFFh	118000h-11FFFFh

34	64/32	220000h-22FFFFh	110000h-117FFFh
33	64/32	210000h-21FFFFh	108000h-10FFFFh
32	64/32	200000h-20FFFFh	100000h-107FFFh
31	64/32	1F0000h-1FFFFFFh	0F8000h-0FBFFFh
30	64/32	1E0000h-1EFFFFh	0F0000h-0F7FFFh
29	64/32	1D0000h-1DFFFFh	0E8000h-0EFFFFFh
28	64/32	1C0000h-1CFFFFh	0E0000h-0E7FFFh
27	64/32	1B0000h-1BFFFFh	0D8000h-0DFFFFh
26	64/32	1A0000h-1AFFFFh	0D0000h-0D7FFFh
25	64/32	190000h-19FFFFh	0C8000h-0CFFFFh
24	64/32	180000h-18FFFFh	0C0000h-0C7FFFh
23	64/32	170000h-17FFFFh	0B8000h-0BFFFFh
22	64/32	160000h-16FFFFh	0B0000h-0B7FFFh
21	64/32	150000h-15FFFFh	0A8000h-0AFFFFFh
20	64/32	140000h-14FFFFh	0A0000h-0A7FFFh
19	64/32	130000h-13FFFFh	098000h-09FFFFh
18	64/32	120000h-12FFFFh	090000h-097FFFh
17	64/32	110000h-11FFFFh	088000h-08FFFFh
16	64/32	100000h-10FFFFh	080000h-087FFFh
15	64/32	0F0000h-0FFFFFFh	078000h-07FFFFh
14	64/32	0E0000h-0EFFFFh	070000h-077FFFh
13	64/32	0D0000h-0DFFFFh	068000h-06FFFFh
12	64/32	0C0000h-0CFFFFh	060000h-067FFFh
11	64/32	0B0000h-0BFFFFh	058000h-05FFFFh
10	64/32	0A0000h-0AFFFFh	050000h-057FFFh
9	64/32	090000h-09FFFFh	048000h-04FFFFh
8	64/32	080000h-08FFFFh	040000h-047FFFh
7	64/32	070000h-07FFFFh	038000h-03FFFFh
6	64/32	060000h-06FFFFh	030000h-037FFFh
5	64/32	050000h-05FFFFh	028000h-02FFFFh
4	64/32	040000h-04FFFFh	020000h-027FFFh
3	64/32	030000h-03FFFFh	018000h-01FFFFh
2	64/32	020000h-02FFFFh	010000h-017FFFh
1	64/32	010000h-01FFFFh	008000h-00FFFFh
0	64/32	000000h-00FFFFh	000000h-007FFFh

**Table 21. Bottom Boot Block Addresses, M29W320DB**

#	Size (KByte/KWord)	Address Range (x8)	Address Range (x16)
66	64/32	3F0000h-3FFFFFh	1F8000h-1FFFFFh
65	64/32	3E0000h-3EFFFFh	1F0000h-1F7FFFh
64	64/32	3D0000h-3DFFFFh	1E8000h-1EFFFFh
63	64/32	3C0000h-3CFFFFh	1E0000h-1E7FFFh
62	64/32	3B0000h-3BFFFFh	1D8000h-1DFFFFh
61	64/32	3A0000h-3AFFFFh	1D0000h-1D7FFFh
60	64/32	390000h-39FFFFh	1C8000h-1CFFFFh
59	64/32	380000h-18FFFFh	1C0000h-1C7FFFh
58	64/32	370000h-37FFFFh	1B8000h-1BFFFFh
57	64/32	360000h-36FFFFh	1B0000h-1B7FFFh
56	64/32	350000h-35FFFFh	1A8000h-1AFFFFh
55	64/32	340000h-34FFFFh	1A0000h-1A7FFFh
54	64/32	330000h-33FFFFh	198000h-19FFFFh
53	64/32	320000h-32FFFFh	190000h-197FFFh
52	64/32	310000h-31FFFFh	188000h-18FFFFh
51	64/32	300000h-30FFFFh	180000h-187FFFh
50	64/32	2F0000h-2FFFFFFh	178000h-17FFFFh
49	64/32	2E0000h-2EFFFFh	170000h-177FFFh
48	64/32	2D0000h-2DFFFFh	168000h-16FFFFh
47	64/32	2C0000h-2CFFFFh	160000h-167FFFh
46	64/32	2B0000h-2BFFFFh	158000h-15FFFFh
45	64/32	2A0000h-2AFFFFh	150000h-157FFFh
44	64/32	290000h-29FFFFh	148000h-14FFFFh
43	64/32	280000h-28FFFFh	140000h-147FFFh
42	64/32	270000h-27FFFFh	138000h-13FFFFh
41	64/32	260000h-26FFFFh	130000h-137FFFh
40	64/32	250000h-25FFFFh	128000h-12FFFFh
39	64/32	240000h-24FFFFh	120000h-127FFFh
38	64/32	230000h-23FFFFh	118000h-11FFFFh
37	64/32	220000h-22FFFFh	110000h-117FFFh
36	64/32	210000h-21FFFFh	108000h-10FFFFh
35	64/32	200000h-20FFFFh	100000h-107FFFh

34	64/32	1F0000h-1FFFFFh	0F8000h-0FBFFFh
33	64/32	1E0000h-1EFFFFh	0F0000h-0F7FFFh
32	64/32	1D0000h-1DFFFFh	0E8000h-0EFFFFh
31	64/32	1C0000h-1CFFFFh	0E0000h-0E7FFFh
30	64/32	1B0000h-1BFFFFh	0D8000h-0DFFFFh
29	64/32	1A0000h-1AFFFFh	0D0000h-0D7FFFh
28	64/32	190000h-19FFFFh	0C8000h-0CFFFFh
27	64/32	180000h-18FFFFh	0C0000h-0C7FFFh
26	64/32	170000h-17FFFFh	0B8000h-0BFFFFh
25	64/32	160000h-16FFFFh	0B0000h-0B7FFFh
24	64/32	150000h-15FFFFh	0A8000h-0AFFFFFh
23	64/32	140000h-14FFFFh	0A0000h-0A7FFFh
22	64/32	130000h-13FFFFh	098000h-09FFFFh
21	64/32	120000h-12FFFFh	090000h-097FFFh
20	64/32	110000h-11FFFFh	088000h-08FFFFh
19	64/32	100000h-10FFFFh	080000h-087FFFh
18	64/32	0F0000h-0FFFFFFh	078000h-07FFFFh
17	64/32	0E0000h-0EFFFFh	070000h-077FFFh
16	64/32	0D0000h-0DFFFFh	068000h-06FFFFh
15	64/32	0C0000h-0CFFFFh	060000h-067FFFh
14	64/32	0B0000h-0BFFFFh	058000h-05FFFFh
13	64/32	0A0000h-0AFFFFh	050000h-057FFFh
12	64/32	090000h-09FFFFh	048000h-04FFFFh
11	64/32	080000h-08FFFFh	040000h-047FFFh
10	64/32	070000h-07FFFFh	038000h-03FFFFh
9	64/32	060000h-06FFFFh	030000h-037FFFh
8	64/32	050000h-05FFFFh	028000h-02FFFFh
7	64/32	040000h-04FFFFh	020000h-027FFFh
6	64/32	030000h-03FFFFh	018000h-01FFFFh
5	64/32	020000h-02FFFFh	010000h-017FFFh
4	64/32	010000h-01FFFFh	008000h-00FFFFh
3	32/16	008000h-00FFFFh	004000h-007FFFh
2	8/4	006000h-007FFFh	003000h-003FFFh
1	8/4	004000h-005FFFh	002000h-002FFFh
0	16/8	000000h-003FFFh	000000h-001FFFh

**APPENDIX B. COMMON FLASH INTERFACE (CFI)**

The Common Flash Interface is a JEDEC approved, standardized data structure that can be read from the Flash memory device. It allows a system software to query the device to determine various electrical and timing parameters, density information and functions supported by the memory. The system can interface easily with the device, enabling the software to upgrade itself when necessary.

When the CFI Query Command is issued the device enters CFI Query mode and the data structure

is read from the memory. Tables 22, 23, 24, 25, 26 and 27 show the addresses used to retrieve the data.

The CFI data structure also contains a security area where a 64 bit unique security number is written (see Table 27, Security Code area). This area can be accessed only in Read mode by the final user. It is impossible to change the security number after it has been written by ST. Issue a Read command to return to Read mode.

**Table 22. Query Structure Overview**

Address		Sub-section Name	Description
x16	x8		
10h	20h	CFI Query Identification String	Command set ID and algorithm data offset
1Bh	36h	System Interface Information	Device timing & voltage information
27h	4Eh	Device Geometry Definition	Flash device layout
40h	80h	Primary Algorithm-specific Extended Query table	Additional information specific to the Primary Algorithm (optional)
61h	C2h	Security Code Area	64 bit unique device number

Note: Query data are always presented on the lowest order data outputs.

**Table 23. CFI Query Identification String**

Address		Data	Description	Value
x16	x8			
10h	20h	0051h		"Q"
11h	22h	0052h	Query Unique ASCII String "QRY"	"R"
12h	24h	0059h		"Y"
13h	26h	0002h	Primary Algorithm Command Set and Control Interface ID code 16 bit	AMD
14h	28h	0000h	ID code defining a specific algorithm	Compatible
15h	2Ah	0040h		
16h	2Ch	0000h	Address for Primary Algorithm extended Query table (see Table 25)	P = 40h
17h	2Eh	0000h		
18h	30h	0000h	Alternate Vendor Command Set and Control Interface ID Code second vendor - specified algorithm supported	NA
19h	32h	0000h		
1Ah	34h	0000h	Address for Alternate Algorithm extended Query table	NA

Note: Query data are always presented on the lowest order data outputs (DQ7-DQ0) only. DQ8-DQ15 are '0'.

**Table 24. CFI Query System Interface Information**

Address		Data	Description	Value
x16	x8			
1Bh	36h	0027h	V <sub>CC</sub> Logic Supply Minimum Program/Erase voltage bit 7 to 4 BCD value in volts bit 3 to 0 BCD value in 100 mV	2.7V
1Ch	38h	0036h	V <sub>CC</sub> Logic Supply Maximum Program/Erase voltage bit 7 to 4 BCD value in volts bit 3 to 0 BCD value in 100 mV	3.6V
1Dh	3Ah	00B5h	V <sub>PP</sub> [Programming] Supply Minimum Program/Erase voltage bit 7 to 4 HEX value in volts bit 3 to 0 BCD value in 100 mV	11.5V
1Eh	3Ch	00C5h	V <sub>PP</sub> [Programming] Supply Maximum Program/Erase voltage bit 7 to 4 HEX value in volts bit 3 to 0 BCD value in 100 mV	12.5V
1Fh	3Eh	0004h	Typical timeout per single byte/word program = 2 <sup>n</sup> $\mu$ s	16 $\mu$ s
20h	40h	0000h	Typical timeout for minimum size write buffer program = 2 <sup>n</sup> $\mu$ s	NA
21h	42h	000Ah	Typical timeout per individual block erase = 2 <sup>n</sup> ms	1s
22h	44h	0000h	Typical timeout for full chip erase = 2 <sup>n</sup> ms	NA
23h	46h	0005h	Maximum timeout for byte/word program = 2 <sup>n</sup> times typical	512 $\mu$ s
24h	48h	0000h	Maximum timeout for write buffer program = 2 <sup>n</sup> times typical	NA
25h	4Ah	0004h	Maximum timeout per individual block erase = 2 <sup>n</sup> times typical	16s
26h	4Ch	0000h	Maximum timeout for chip erase = 2 <sup>n</sup> times typical	NA

**Table 25. Device Geometry Definition**

Address		Data	Description	Value
x16	x8			
27h	4Eh	0016h	Device Size = $2^n$ in number of bytes	4 MByte
28h 29h	50h 52h	0002h 0000h	Flash Device Interface Code description	x8, x16 Async.
2Ah 2Bh	54h 56h	0000h 0000h	Maximum number of bytes in multi-byte program or page = $2^n$	NA
2Ch	58h	0004h	Number of Erase Block Regions within the device. It specifies the number of regions within the device containing contiguous Erase Blocks of the same size.	4
2Dh 2Eh	5Ah 5Ch	0000h 0000h	Region 1 Information Number of identical size erase block = 0000h+1	1
2Fh 30h	5Eh 60h	0040h 0000h	Region 1 Information Block size in Region 1 = 0040h * 256 byte	16 Kbyte
31h 32h	62h 64h	0001h 0000h	Region 2 Information Number of identical size erase block = 0001h+1	2
33h 34h	66h 68h	0020h 0000h	Region 2 Information Block size in Region 2 = 0020h * 256 byte	8 Kbyte
35h 36h	6Ah 6Ch	0000h 0000h	Region 3 Information Number of identical size erase block = 0000h+1	1
37h 38h	6Eh 70h	0080h 0000h	Region 3 Information Block size in Region 3 = 0080h * 256 byte	32 Kbyte
39h 3Ah	72h 74h	003Eh 0000h	Region 4 Information Number of identical-size erase block = 003Eh+1	63
3Bh 3Ch	76h 78h	0000h 0001h	Region 4 Information Block size in Region 4 = 0100h * 256 byte	64 Kbyte

**Table 26. Primary Algorithm-Specific Extended Query Table**

Address		Data	Description	Value
x16	x8			
40h	80h	0050h		"P"
41h	82h	0052h	Primary Algorithm extended Query table unique ASCII string "PRI"	"R"
42h	84h	0049h		"I"
43h	86h	0031h	Major version number, ASCII	"1"
44h	88h	0030h	Minor version number, ASCII	"0"
45h	8Ah	0000h	Address Sensitive Unlock (bits 1 to 0) 00 = required, 01 = not required Silicon Revision Number (bits 7 to 2)	Yes
46h	8Ch	0002h	Erase Suspend 00 = not supported, 01 = Read only, 02 = Read and Write	2
47h	8Eh	0001h	Block Protection 00 = not supported, x = number of sectors in per group	1
48h	90h	0001h	Temporary Block Unprotect 00 = not supported, 01 = supported	Yes
49h	92h	0004h	Block Protect /Unprotect 04 = M29W400B	4
4Ah	94h	0000h	Simultaneous Operations, 00 = not supported	No
4Bh	96h	0000h	Burst Mode, 00 = not supported, 01 = supported	No
4Ch	98h	0000h	Page Mode, 00 = not supported, 01 = 4 page word, 02 = 8 page word	No
4Dh	9Ah	00B5h	V <sub>PP</sub> Supply Minimum Program/Erase voltage bit 7 to 4 HEX value in volts bit 3 to 0 BCD value in 100 mV	11.5V
4Eh	9Ch	00C5h	V <sub>PP</sub> Supply Minimum Program/Erase voltage bit 7 to 4 HEX value in volts bit 3 to 0 BCD value in 100 mV	12.5V
4Fh	9Eh	000xh	Top/Bottom Boot Block Flag 02h = Bottom Boot device, 03h = Top Boot device	—

**Table 27. Security Code Area**

Address		Data	Description
x16	x8		
61h	C3h, C2h	XXXX	
62h	C5h, C4h	XXXX	
63h	C7h, C6h	XXXX	
64h	C9h, C8h	XXXX	64 bit: unique device number

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